

Is Silicon Age Coming to an End...?

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END OF THE WORLD 2012

16 days until December 21, 2012



- 2010- , ETHZ, Zürich (CH)
Senior Research Scientist



- 2007-2010, EMPA, Dübendorf (CH)
Research Scientist



- 2005-2007, EPFL, Lausanne (CH)
Scientific Collaborator



- 2002-2005, PSI, Villigen (CH)
Postdoctoral Scientist



- 1998-2002, TU-Delft, Delft (NL)
2002 PhD
Research Assistant and PhD student



- 1996-1998, NIRDIMT, Cluj-Napoca (RO)
Research Assistant



- 1995-1996, EPFL, Lausanne (CH)
Grant from European Physical Society



- 1990-1995 “Babeş-Bolyai” Univ, Cluj-Napoca (RO)
1995 Engineer in Physics

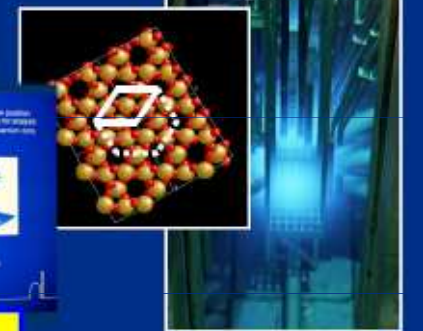
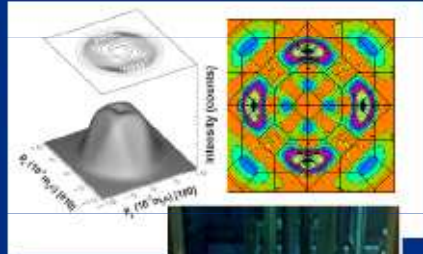
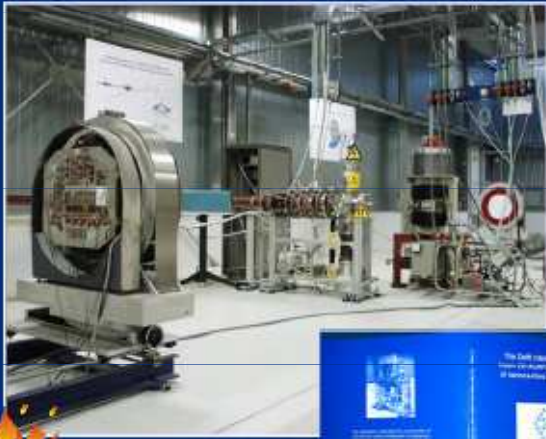


Victor Babeş – *one of the earliest bacteriologists*
(19th century)

Janos Bolyai – *one of the founders of non-euclidian geometry*
(19th century)



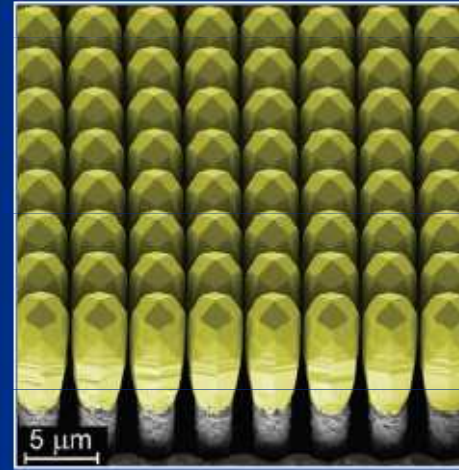
Positron Annihilation 2D-ACAR



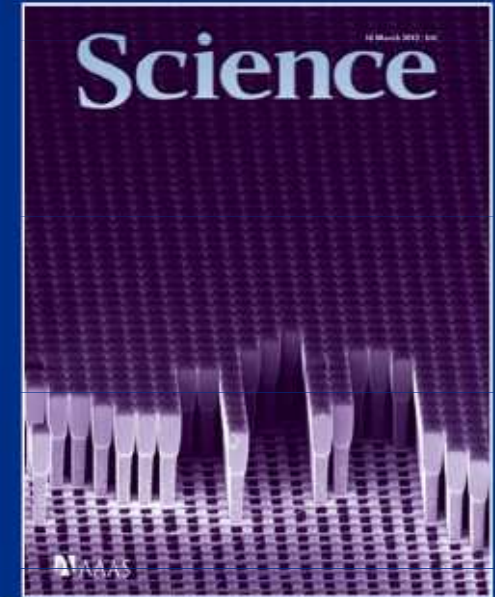
TU Delft
Delft University of Technology



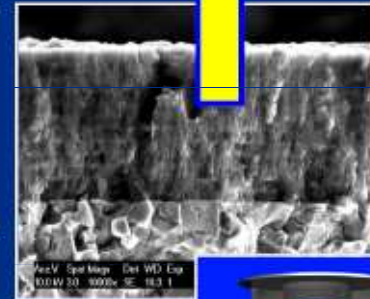
Si/Ge Heteroepitaxy



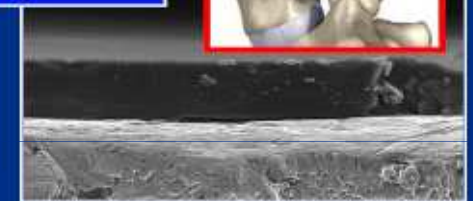
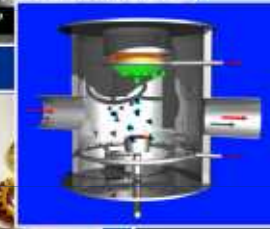
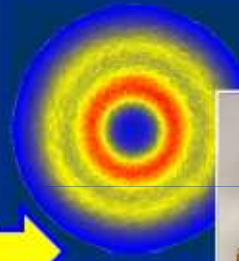
ETH
Eidgenössische Technische Hochschule Zürich
Swiss Federal Institute of Technology Zurich



PSI
PAUL SCHERRER INSTITUT



EMPA
PROTECTIVE COATINGS



LET THERE BE LIGHT ...

EPFL
ÉCOLE POLYTECHNIQUE FÉDÉRALE DE LAUSANNE

Laboratory for **Academic Ranking of World Universities in Natural Sciences and Mathematics - 2012**

PHYSICS OF M

<http://www.>

World Rank	Institution	Country /Region	Total Score
1	Harvard University		100
2	University of California, Berkeley		95.6
3	Princeton University		93
4	California Institute of Technology		92.8
5	Massachusetts Institute of Technology (MIT)		91
6	University of Cambridge		90.5
7	Stanford University		90.2
8	Swiss Federal Institute of Technology Zurich		74.7
9	The University of Tokyo		73.1
10	University of California, Los Angeles		72.8
11	Columbia University		71.6
12	University of Colorado at Boulder		71.4
12	University of Oxford		71.4
14	Cornell University		69

von
el

nd Time

21 Nobel Prize Laureates of ETH Zürich

W.K. Röntgen
Physics 1901



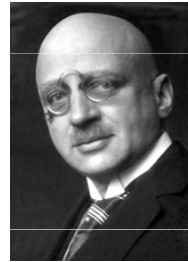
A. Werner
Chemistry 1913



R. Willstätter
Chemistry 1915



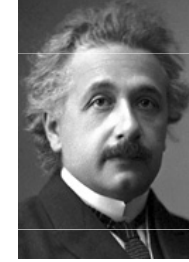
F. Haber
Chemistry 1918



C.-E. Guilleme
Physics 1918



A. Einstein
Physics 1921



P. Debye
Chemistry 1936



R. Kuhn
Chemistry 1938



L. Ruzicka
Chemistry 1938



O. Stern
Physics 1943



W. Pauli
Physics 1945



T. Reichstein
Medicine 1950



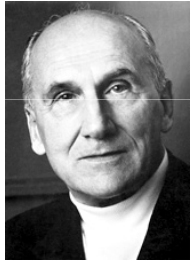
F. Bloch
Physics 1952



H. Staudinger
Chemistry 1953



V. Prelog
Chemistry 1975



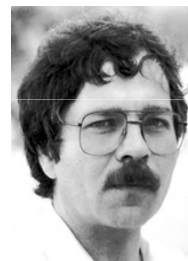
W. Arber
Medicine 1978



H. Rohrer
Physics 1986



G. Bednorz
Physics 1987



A. Müller
Physics 1987



R. Ernst
Chemistry 1991



K. Wüthrich
Chemistry 2002



10 Chemistry, 9 Physics, 2 Medicine

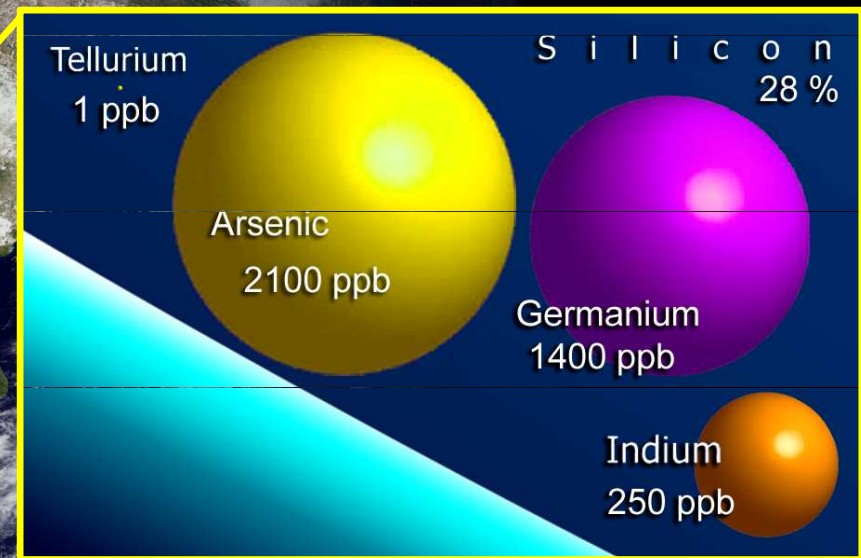
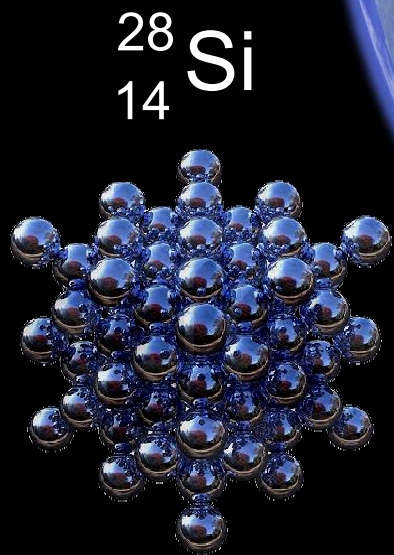
The Age of Silicon



Why Silicon?

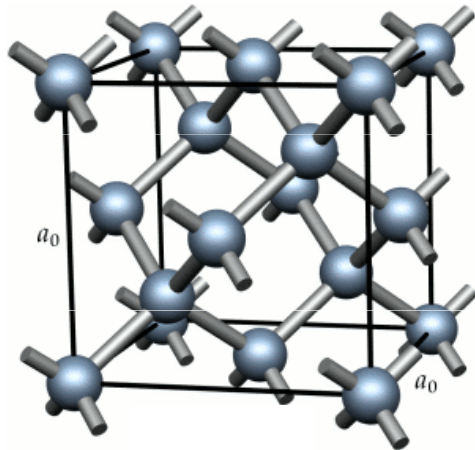
- abundant
- cheap

- well-known to mankind
(SiO_2 : sand, glass)

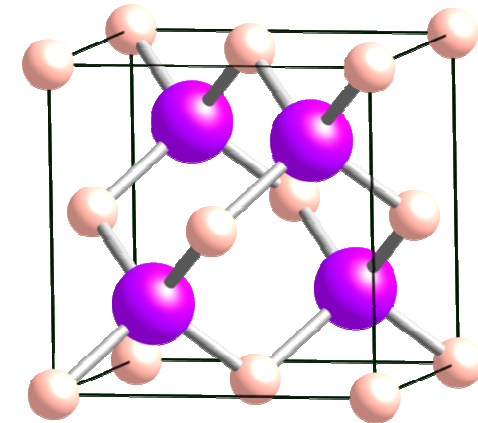
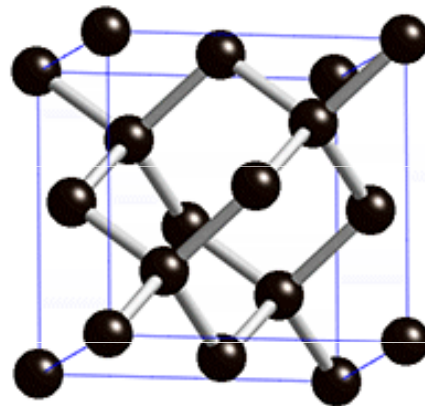


- amazing mechanical, chemical and electronical properties

Crystal Structures

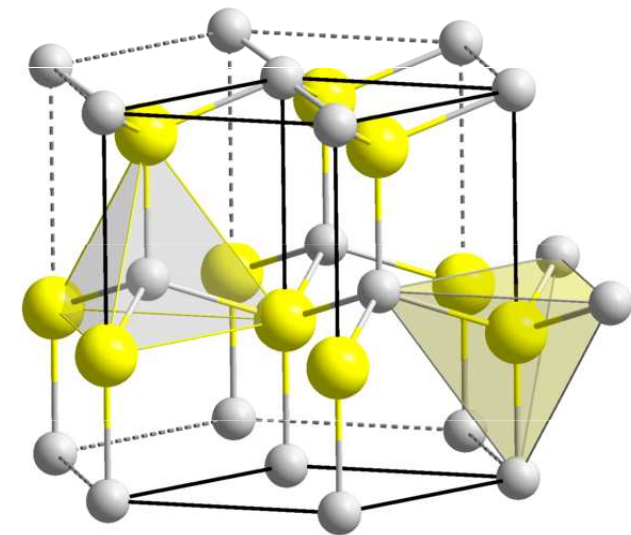


Diamond Structure
(Si, Ge)



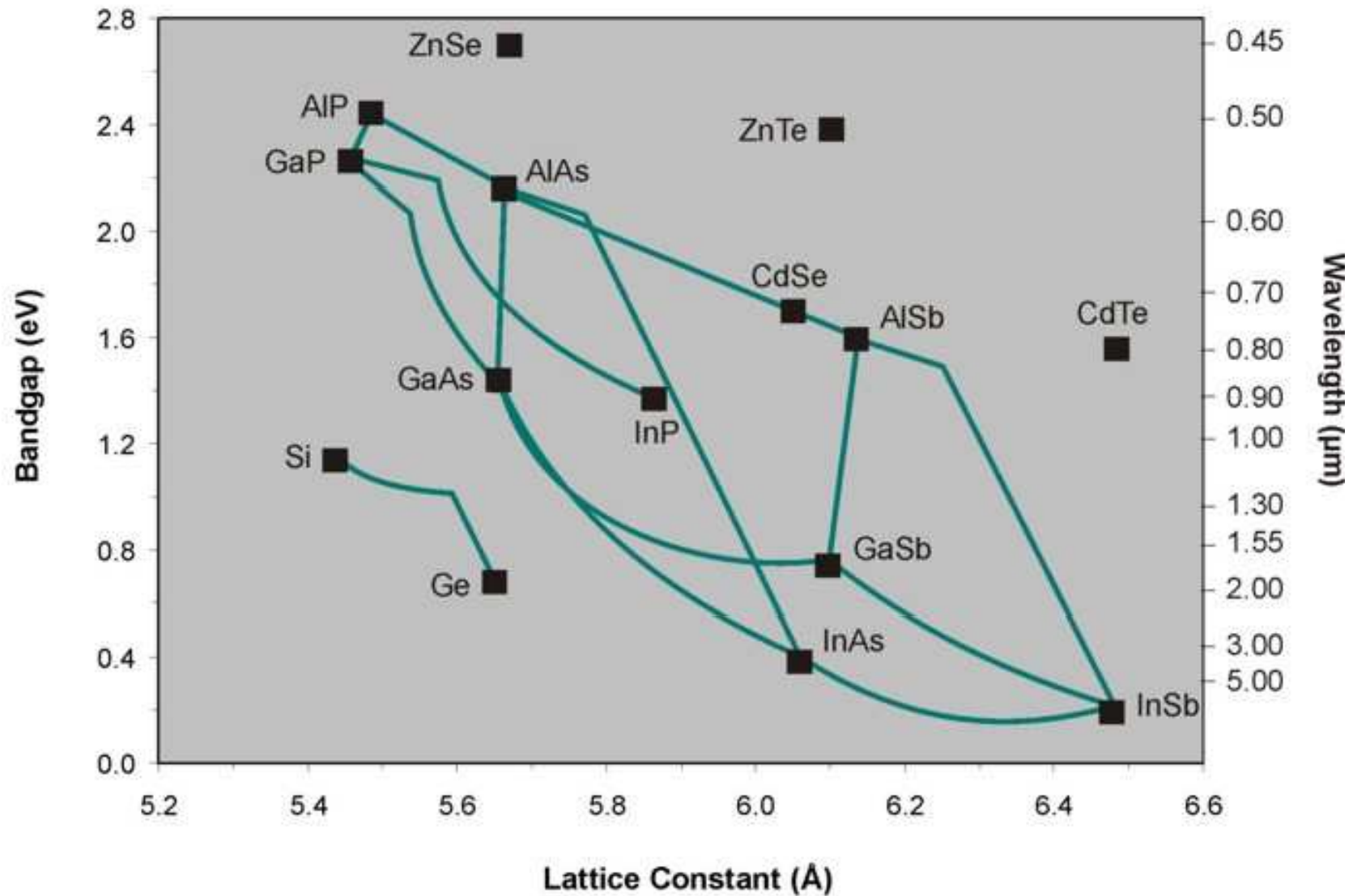
Zincblende Structure
(GaAs, InP, GaP, etc.)

I	II	III	IV	V	VI	VII
	Be	B	C	N	O	F
	Mg	Al	Si	P	S	Cl
Cu	Zn	Ga	Ge	As	Se	Br
Ag	Cd	In	Sn	Sb	Te	I
	Hg	Tl	Pb	Bi		

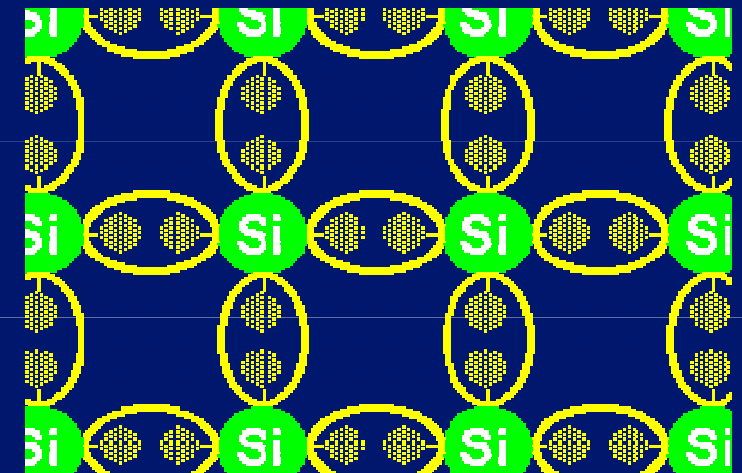
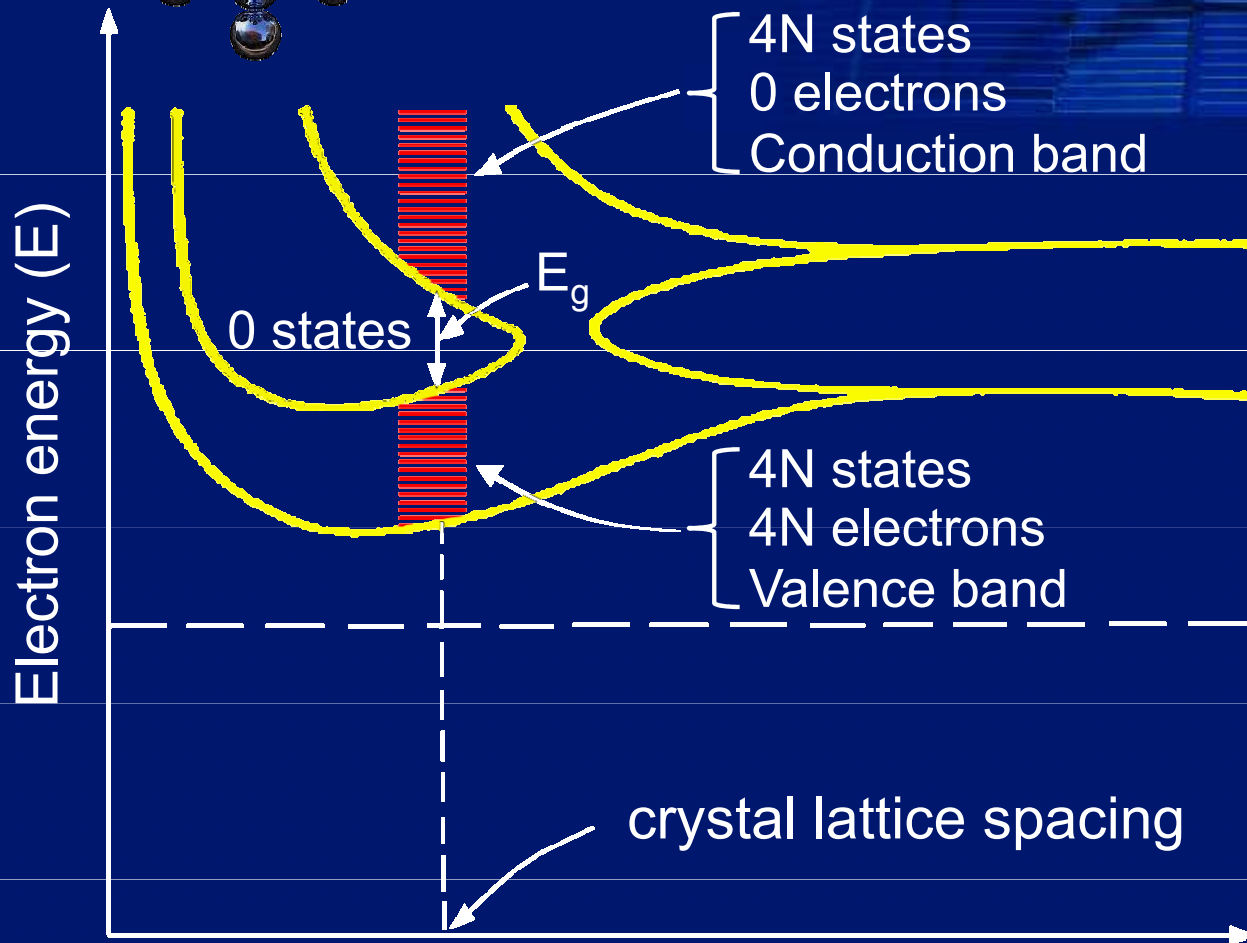
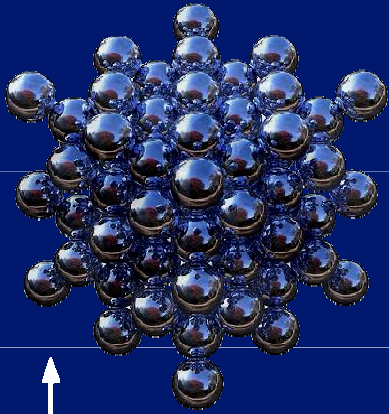


Wurtzite Structure
(GaN, AlN, CdS, BN, etc.)

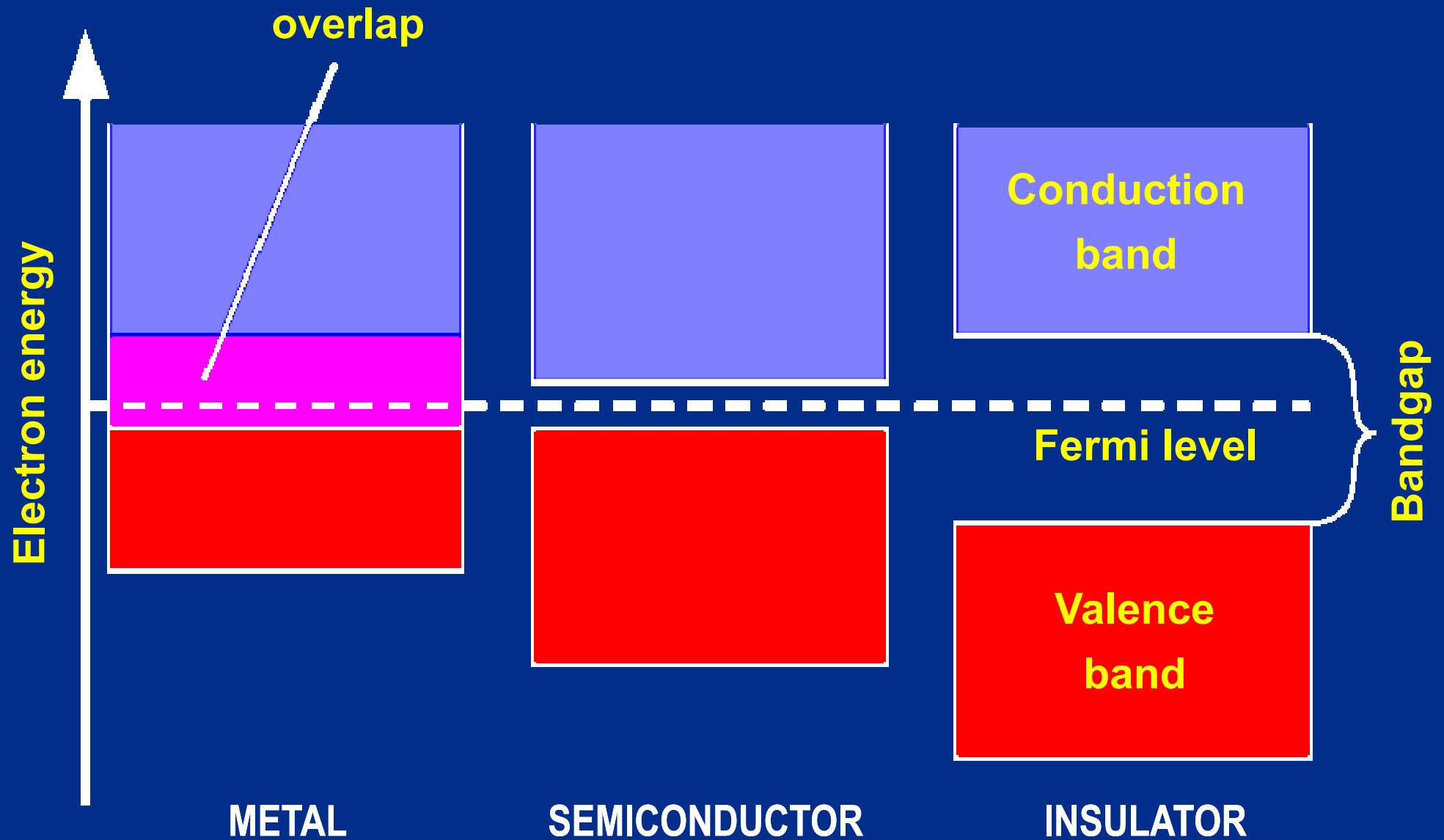
Tetrahedrally Bonded Semiconductors



From Atomic Levels to Band Structures

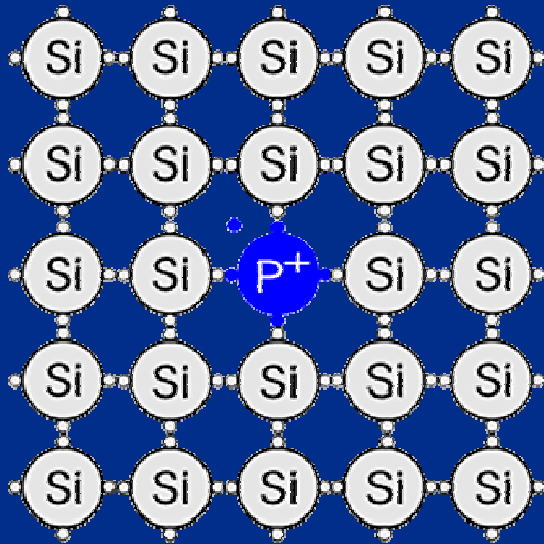


From Band Structures to Different Materials

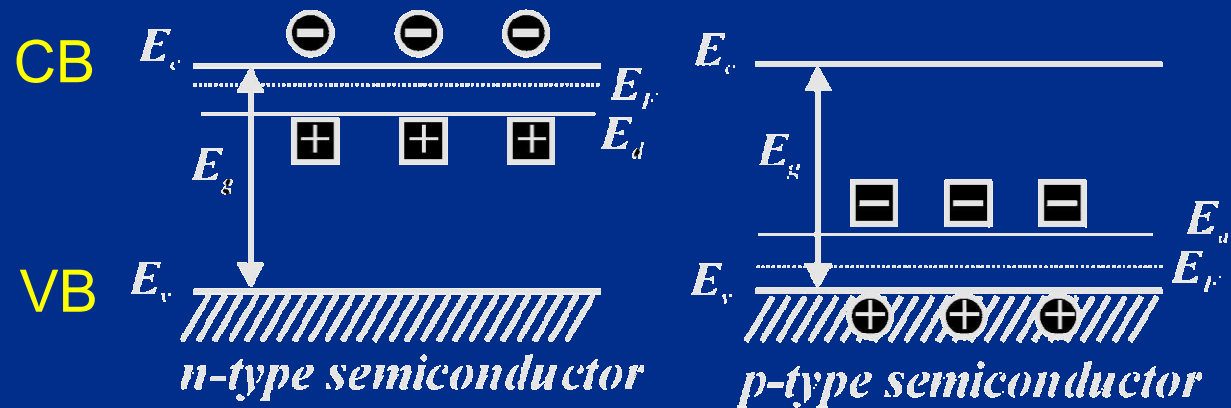
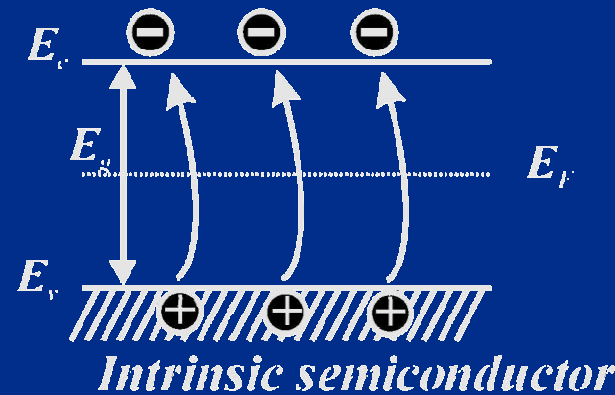
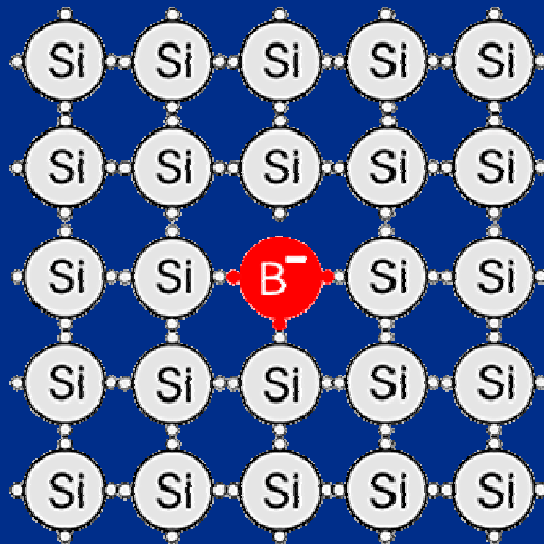


Semiconductor Doping

n-type semiconductor



p-type semiconductor



- ⊖ Electrons in CB (mobile)
- ⊕ Holes in VB (mobile)
- ⊕ Positive ions (immobile donors)
- ⊖ Negative ions (immobile acceptors)

Transistor Effect

J. Bardeen, W. Shockley,
W. Brattain (1947, Bell Labs)

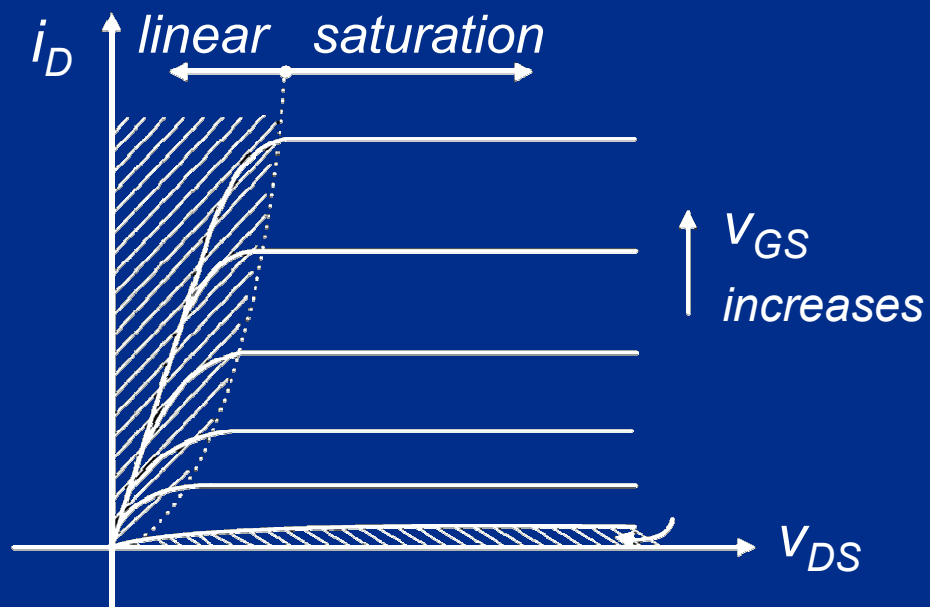
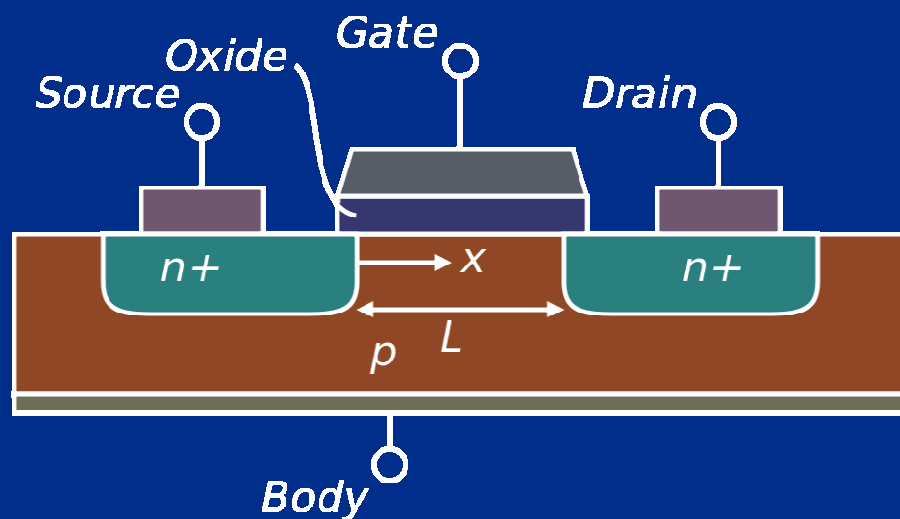
Nobel: 1956



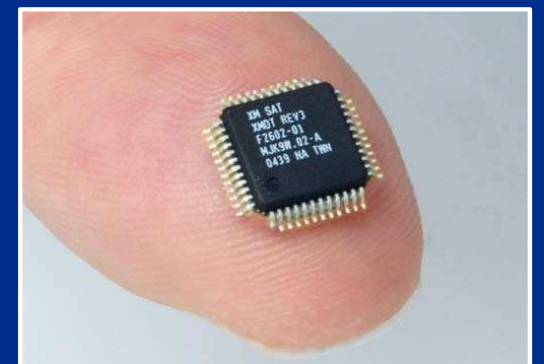
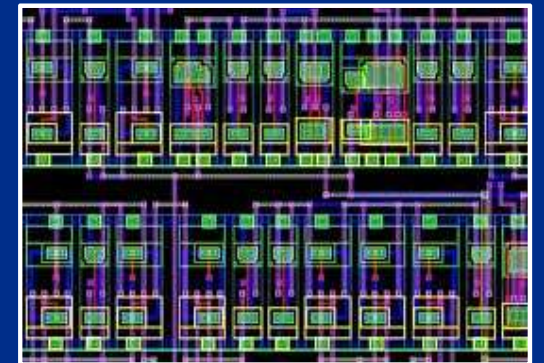
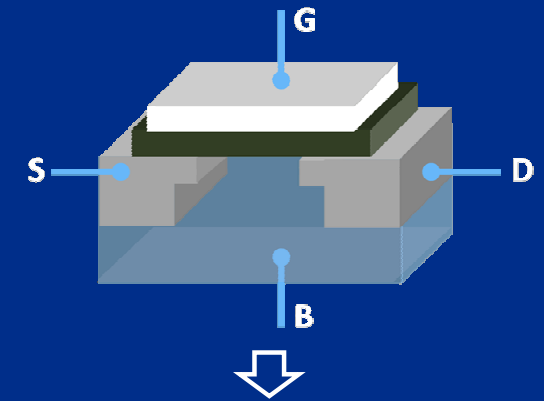
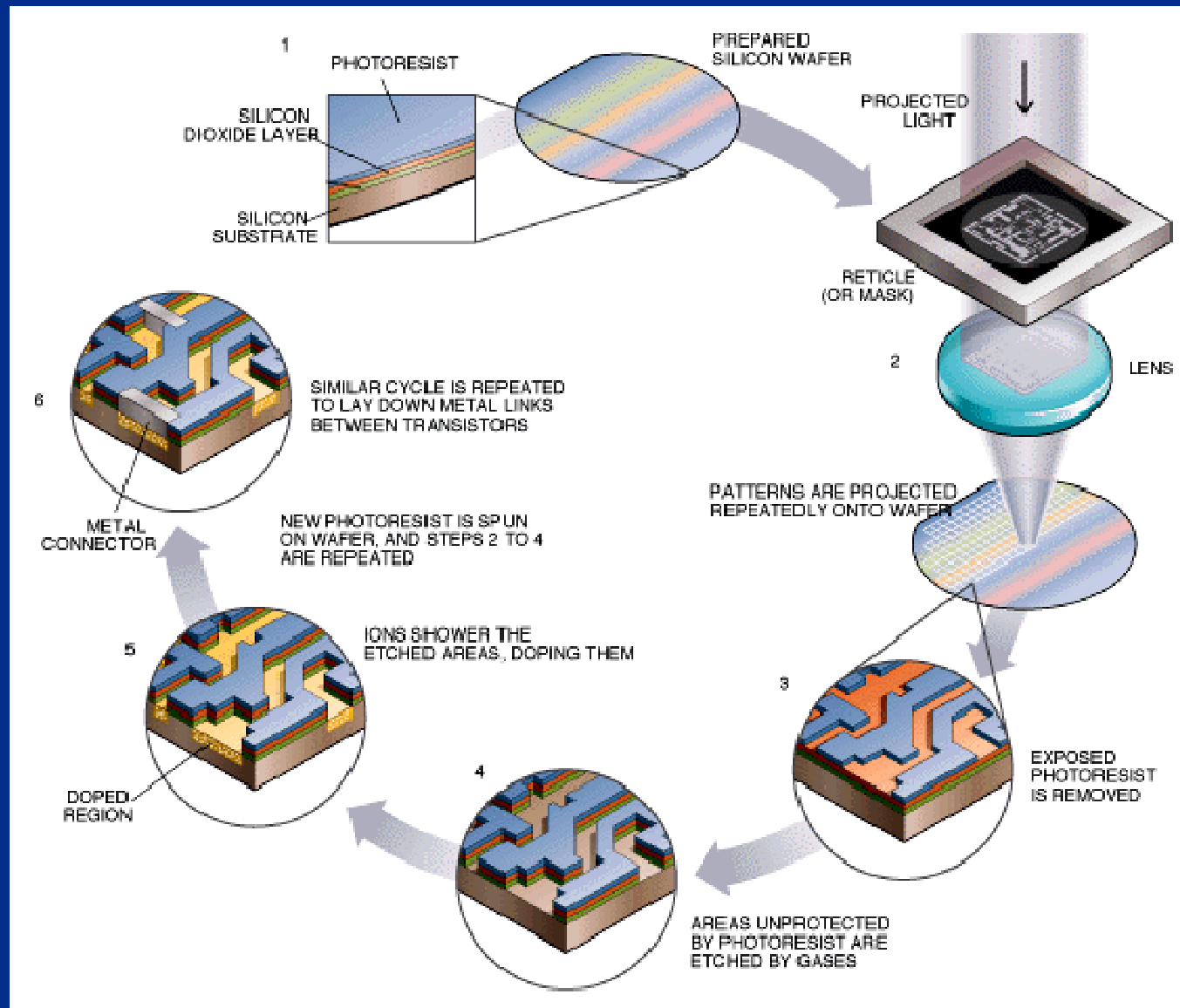
Ge Transistor



nMOSFET



From Transistor to CMOS Devices



Extending Moore's Law beyond Silicon

A. Geim K. Novoselov

(Nobel: 2010)



Graphene

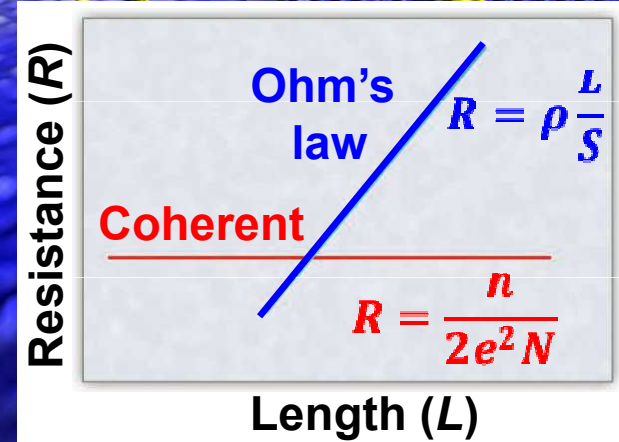


SCIENCE 335, 64 (2012)
"Ohm's law survives to the Atomic Scale"



M. Kako

M. Simmons et al.



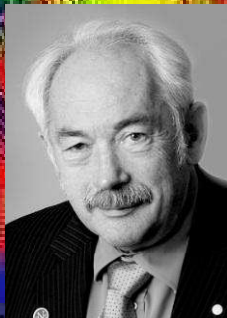
"Moore's law will collapse"

BREAKTHROUGH

Spintronics

A. Fert P. Grünberg

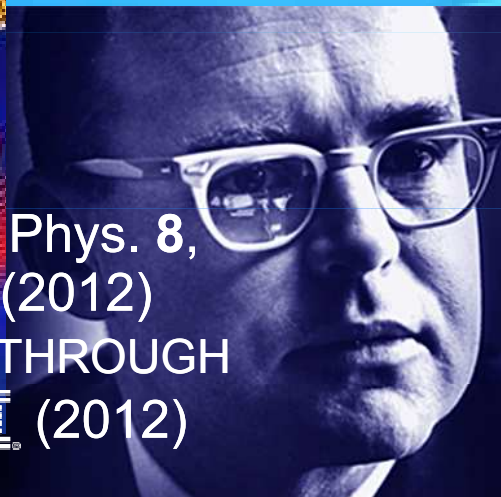
(Nobel: 2007)



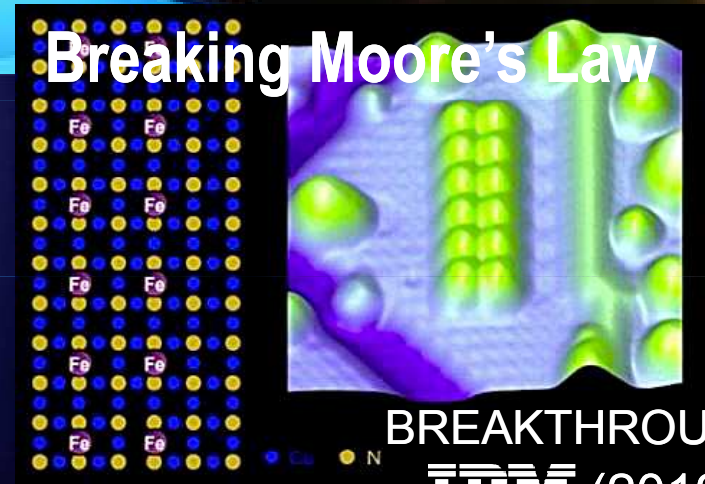
Nature Phys. 8, 757 (2012)

BREAKTHROUGH

IBM (2012)



Breaking Moore's Law

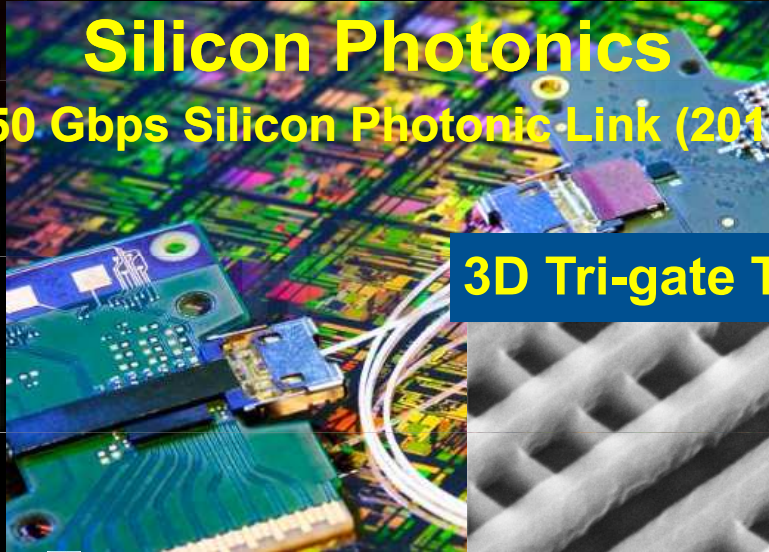


BREAKTHROUGH

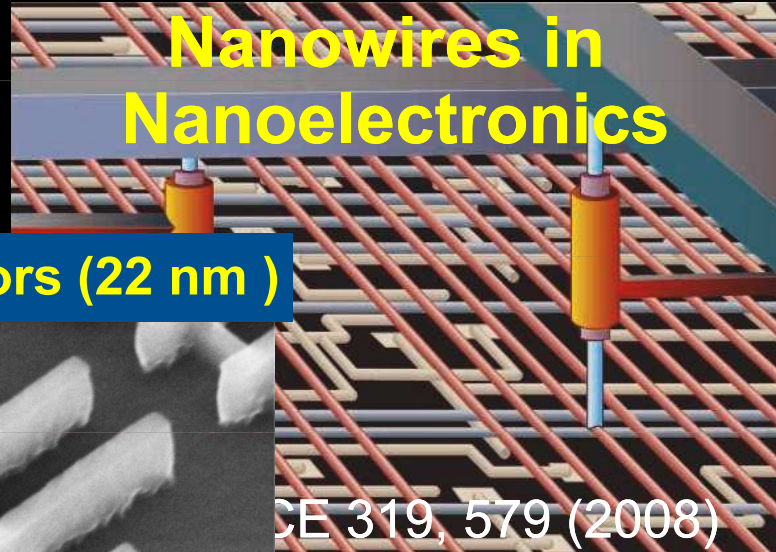
IBM (2012)

Silicon Photonics

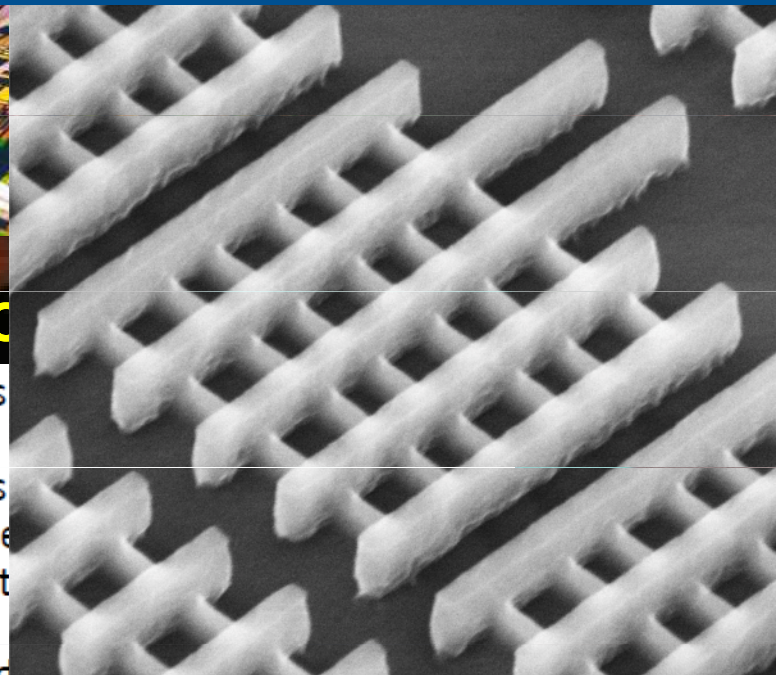
50 Gbps Silicon Photonic Link (2010)



Nanowires in Nanoelectronics



3D Tri-gate Transistors (22 nm)



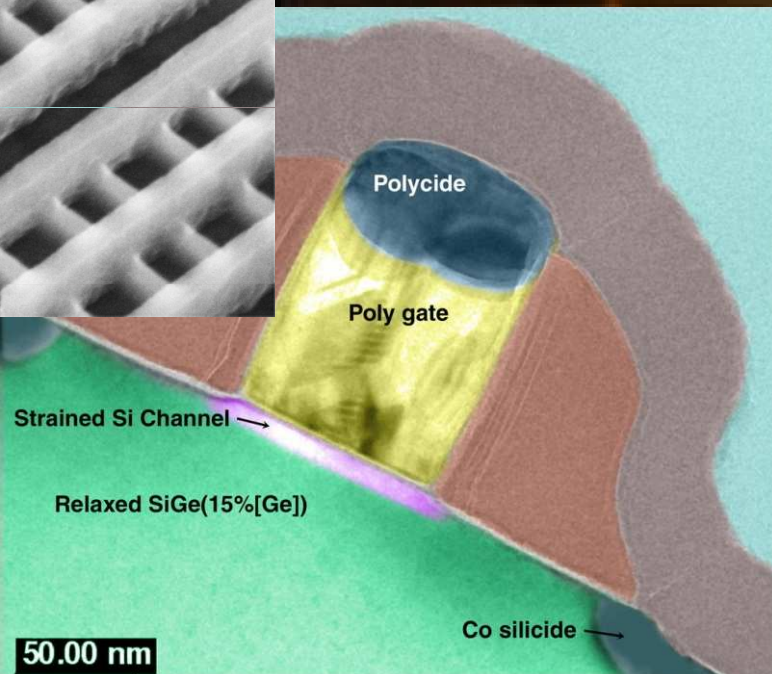
CE 319, 579 (2008)



BREAKTHROUGHS

- February 2004: world's first silicon modulator
- February 2005: world's first wave silicon Raman laser
- April 2005: world's first silicon modulator
- September 2006: world's first hybrid silicon laser
- July 2007: world's first 40 Gbps silicon modulator
- August 2007: world's first 40 Gbps PIN photodetector
- December 2008: world's first 340 GHz Gain*BW avalanche photodetector (APD)

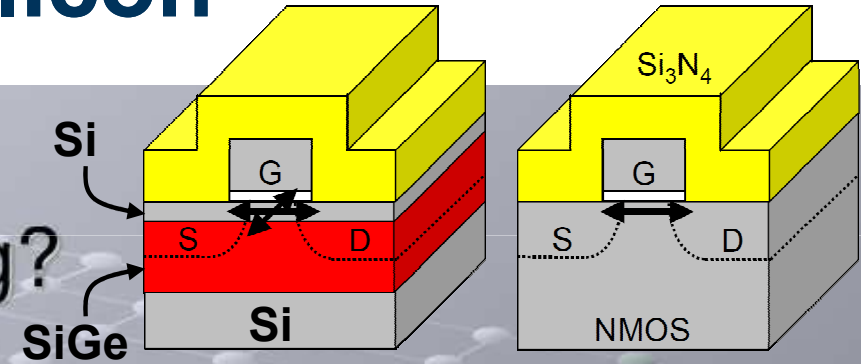
Silicon (90 → 32 nm)



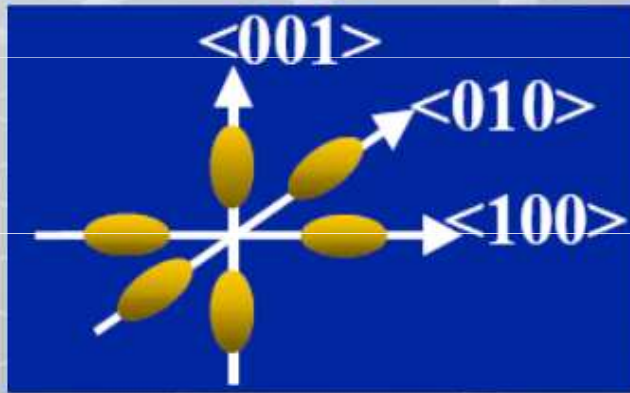
Strained Silicon

Biaxial

Uniaxial

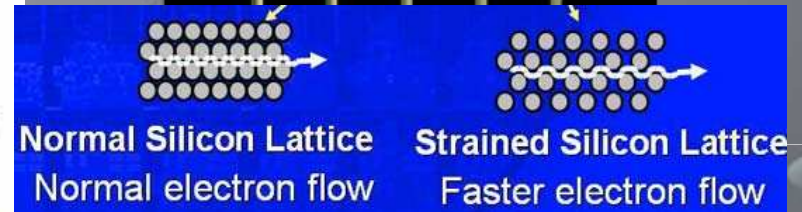
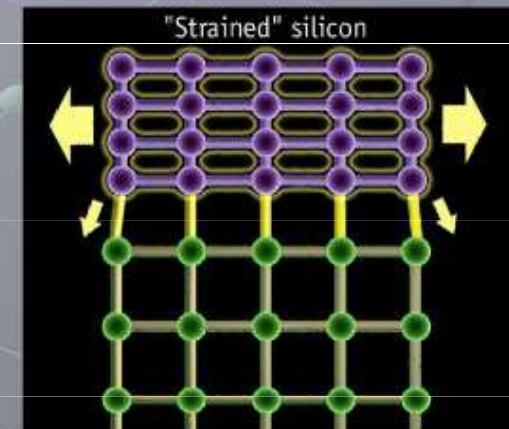
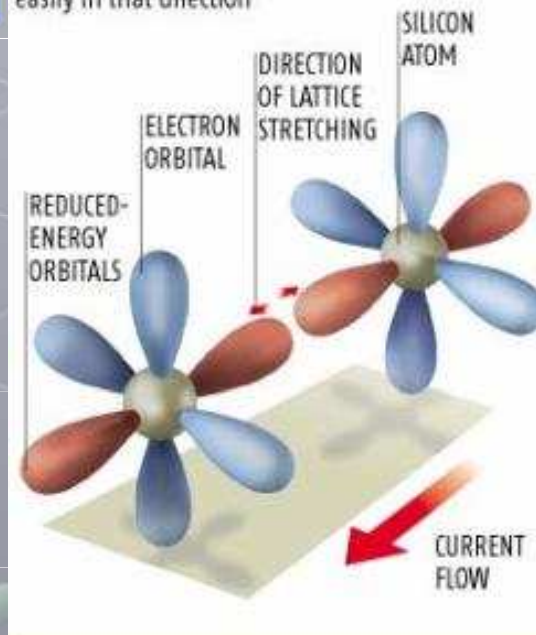
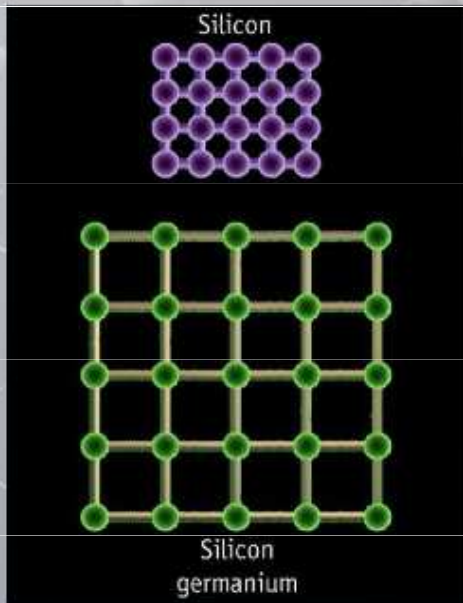
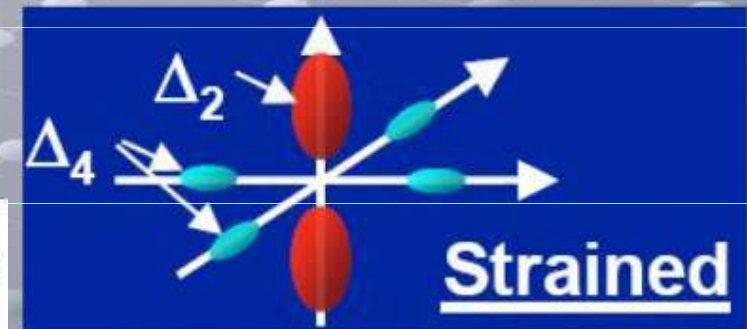


● So, what is actually happening?



FASTER CHIPS

Stretching the silicon lattice reduces the energy of certain orbitals, allowing electrons to move more easily in that direction



International Roadmap for Semiconductors

More than Moore: Diversification

Analog/RF

Passives

HV
Power

Sensors
Actuators

Biochips

More Moore: Miniaturization

Baseline CMOS: CPU, Memory, Logic

130nm

90nm

65nm

45nm

32nm

22nm

...

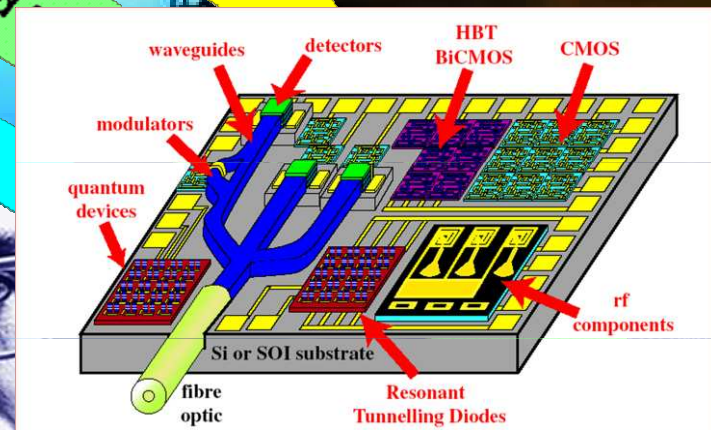
Interacting with people and environment

Non-digital content
System-in-package
(SiP)

Combining SoC and

Information
Processing

Digital content
System-on-chip
(SoC)

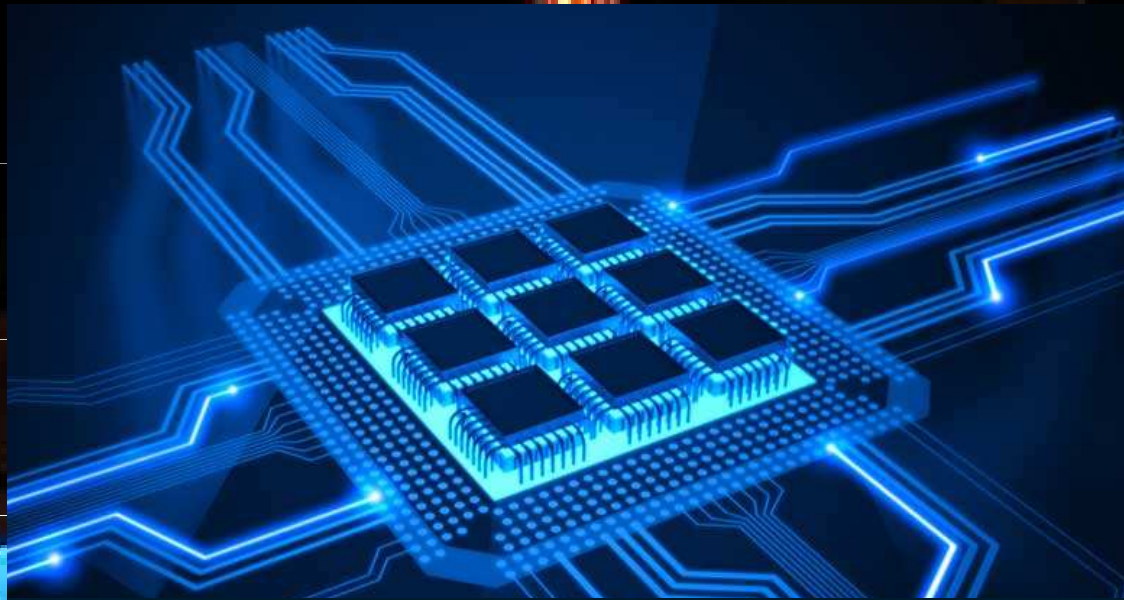


Beyond CMOS

"The integrated silicon chip or system-on-a-chip of the future"



Extending Moore's Law beyond Silicon



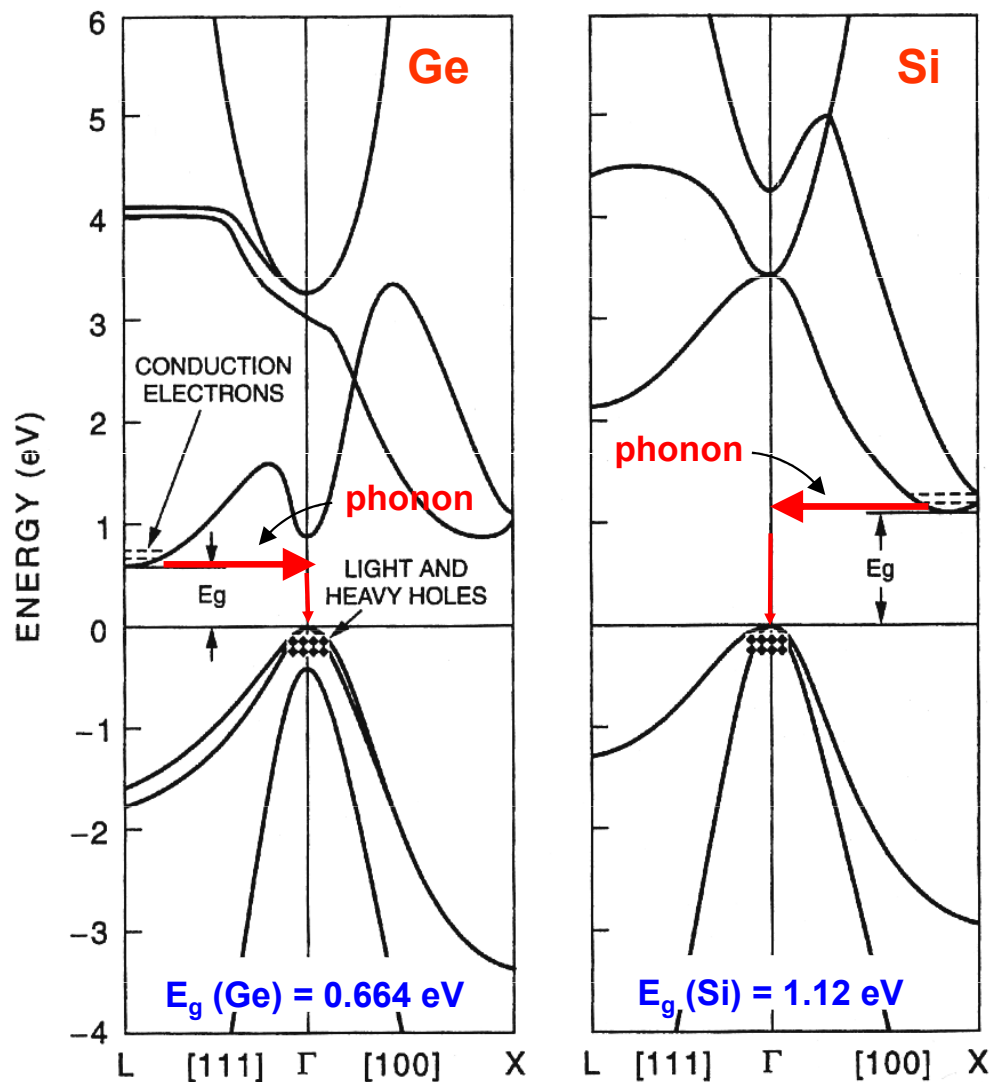
Extending Si technology to other semiconducting materials with optical and electrical properties beyond Si.



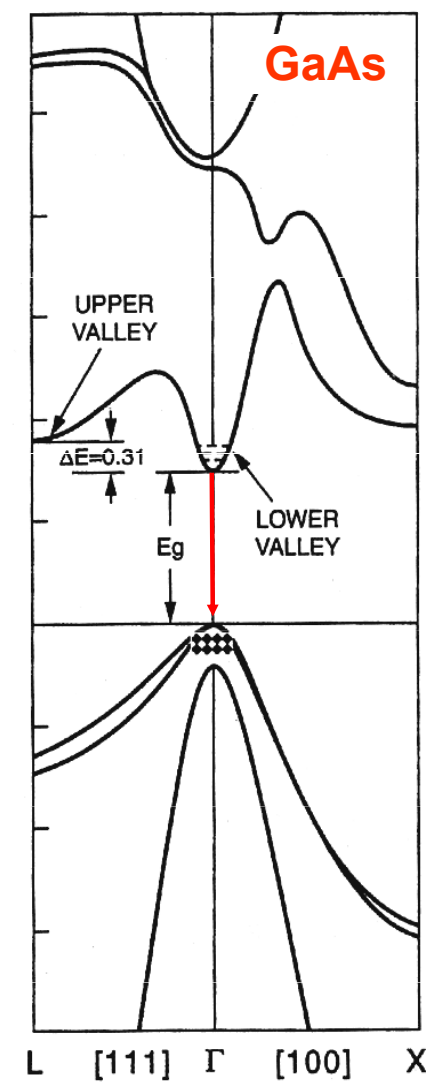
From Microelectronics to Optoelectronics

Si: Inefficient at emitting light (interband transitions involve momentum transfer, i.e., the heat-generating process for electron-hole recombination dominates)

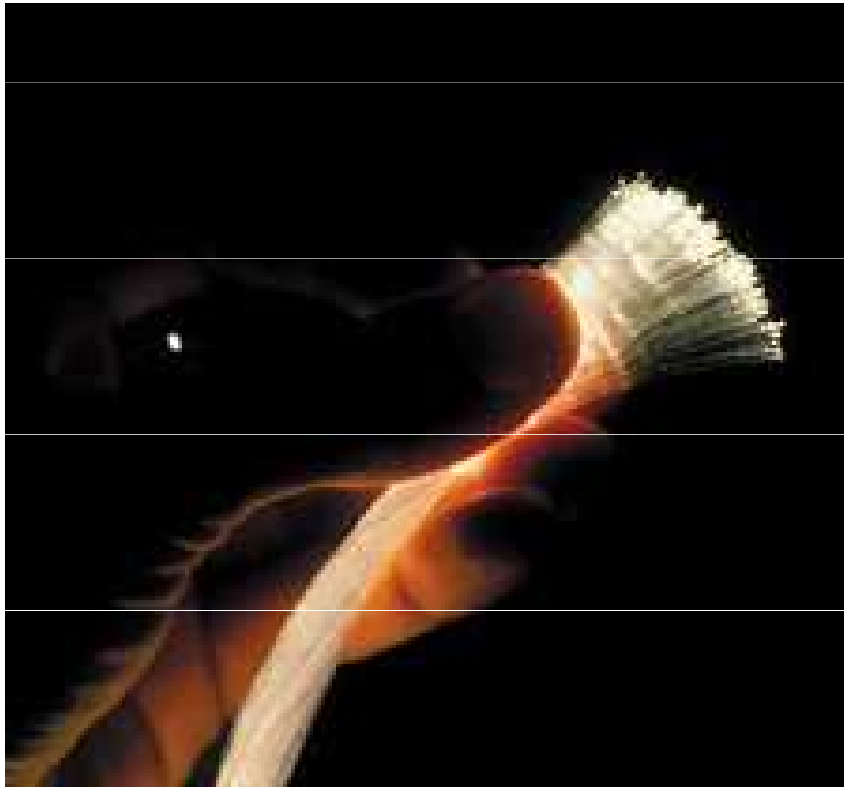
Indirect bandgap semiconductor



Direct bandgap semiconductor



Squeeze Light out of Silicon



Interband

- Ge-dots
- Er-doped Si
- Short period superlattices
- Porous Si
- Si nanocrystals
- Strained Si

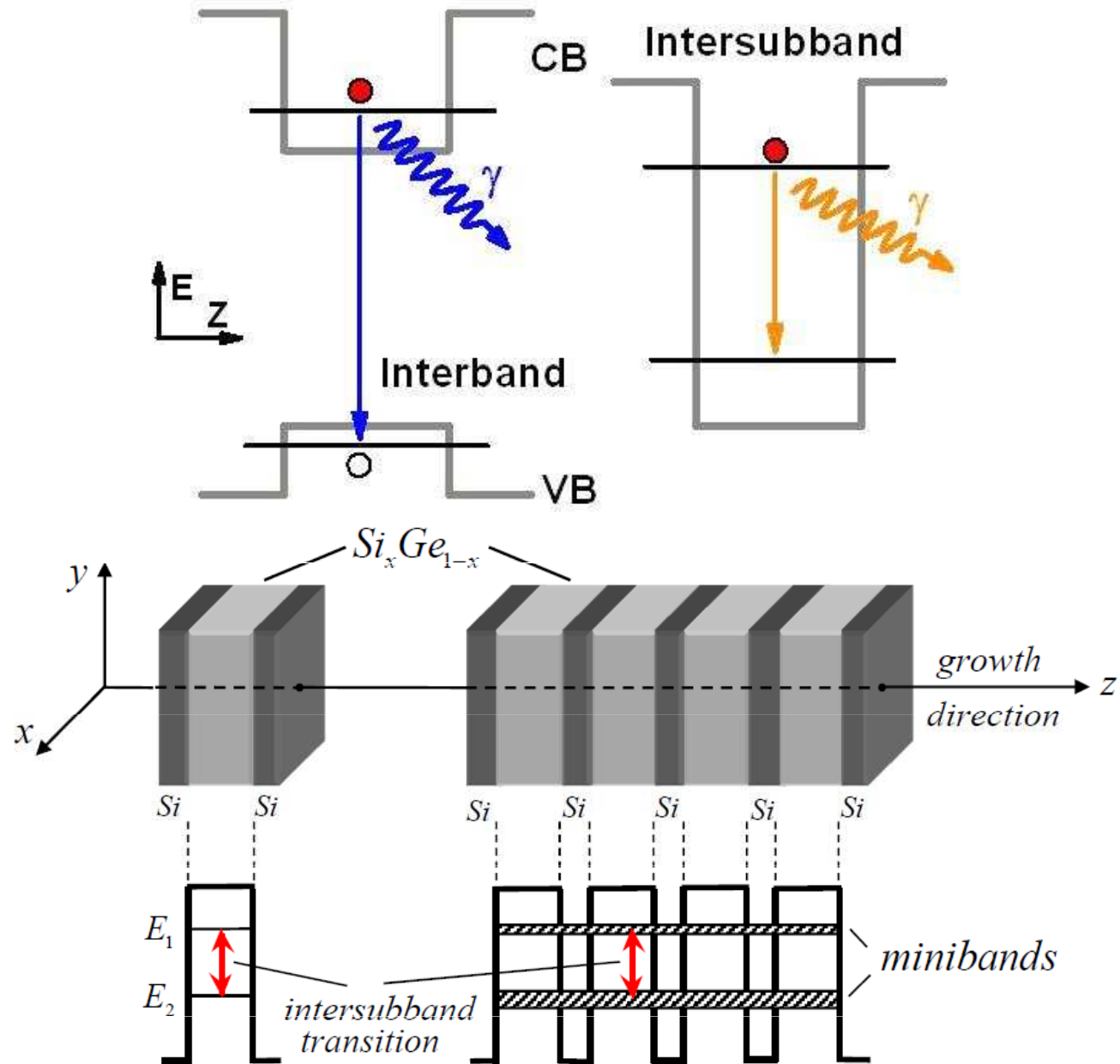
Intersubband

- Quantum Cascade Laser (QCL)

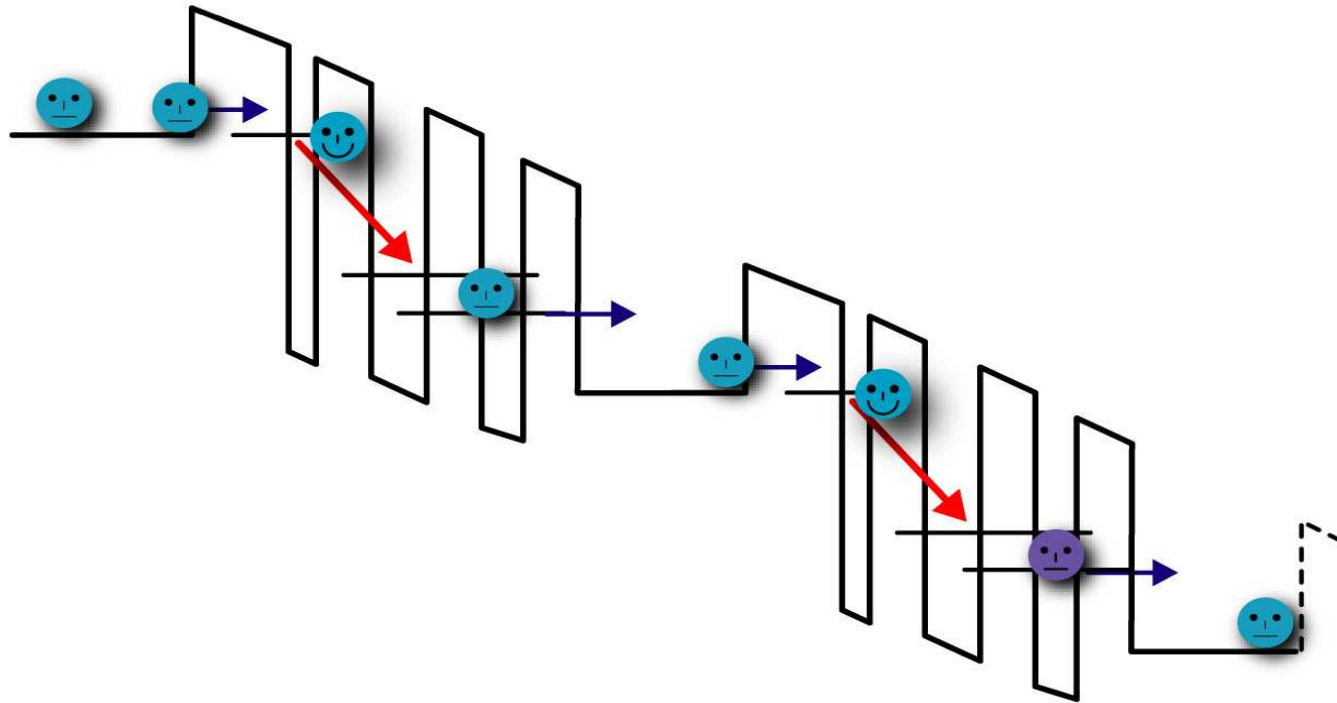
“A silicon laser would revolutionize telecommunications, electronics and computing. Squeezing light out of silicon is no easy task, but researchers are becoming more optimistic about its light-emitting abilities.”

Nature **409**, 974 - 976 (2001)

Interband vs. Intersubband Transitions



Quantum Cascade Laser (QCL)



Cascade: Multiple repetition of active region

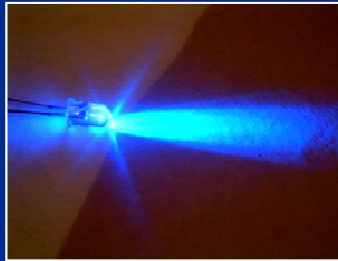
➡ Multiple photons from one electron

Theoretical prediction: R.F. Kazarinov and R.A. Suris, *Fiz. Tekh. Poluvrodvn.* **5**, 797-800 (1971)

Design for III-V compounds (InGaAs/InAlAs): J. Faist et al., *Science* **264**, 533 (1994).

Bridging Optoelectronics and Microelectronics

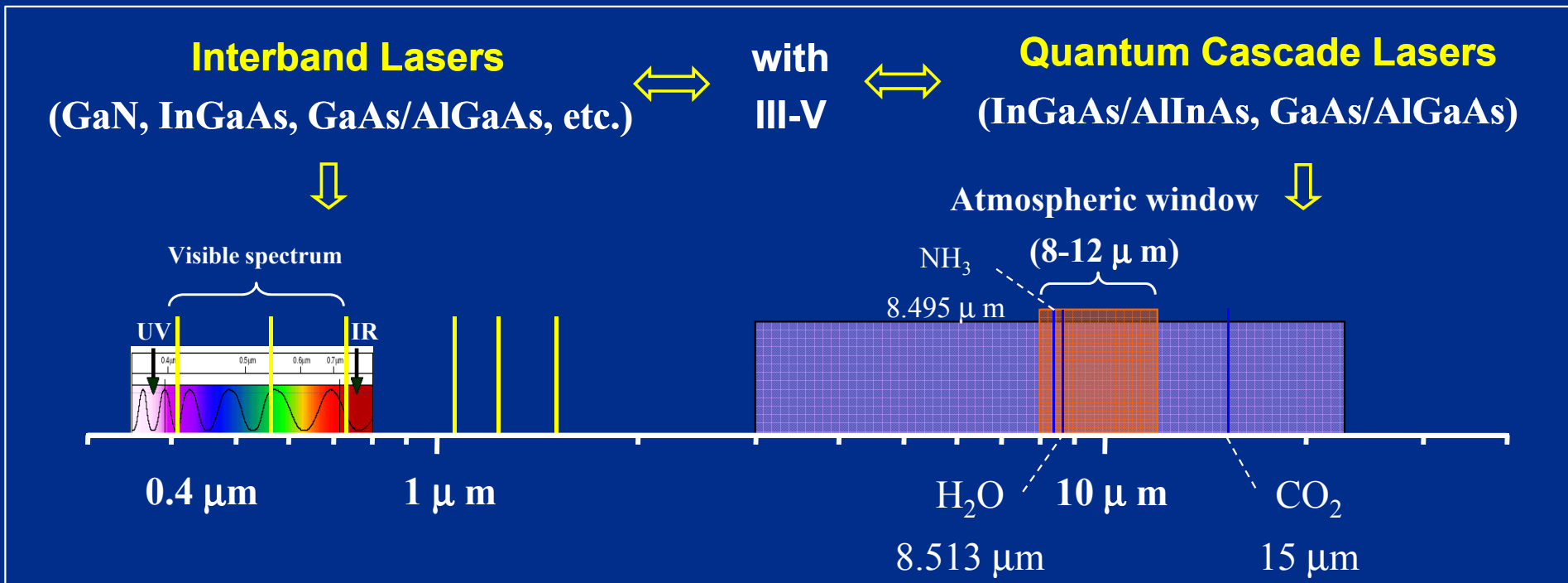
OPTO ↔ ELECTRONICS



III-V material



Silicon

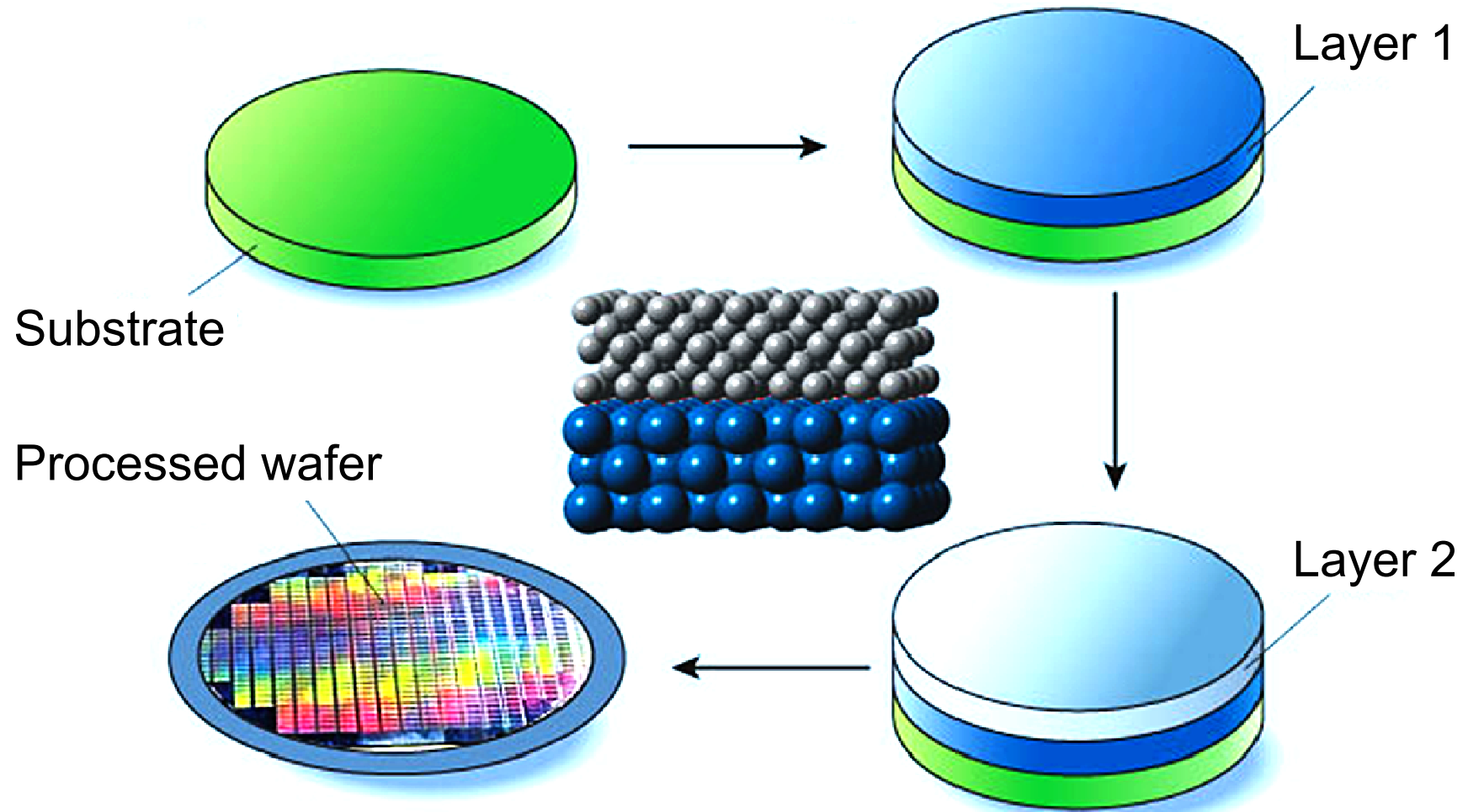


Not possible
(indirect bandgap material)

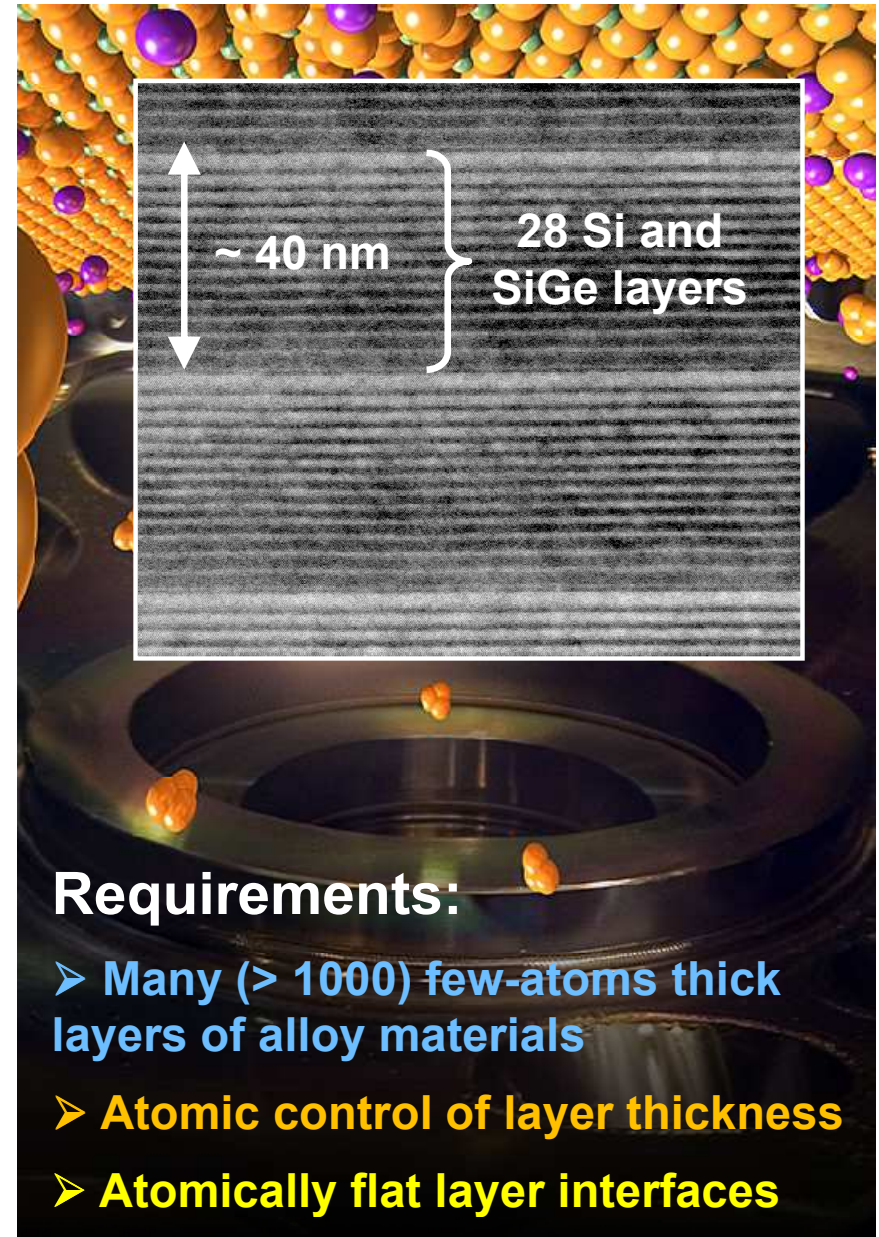
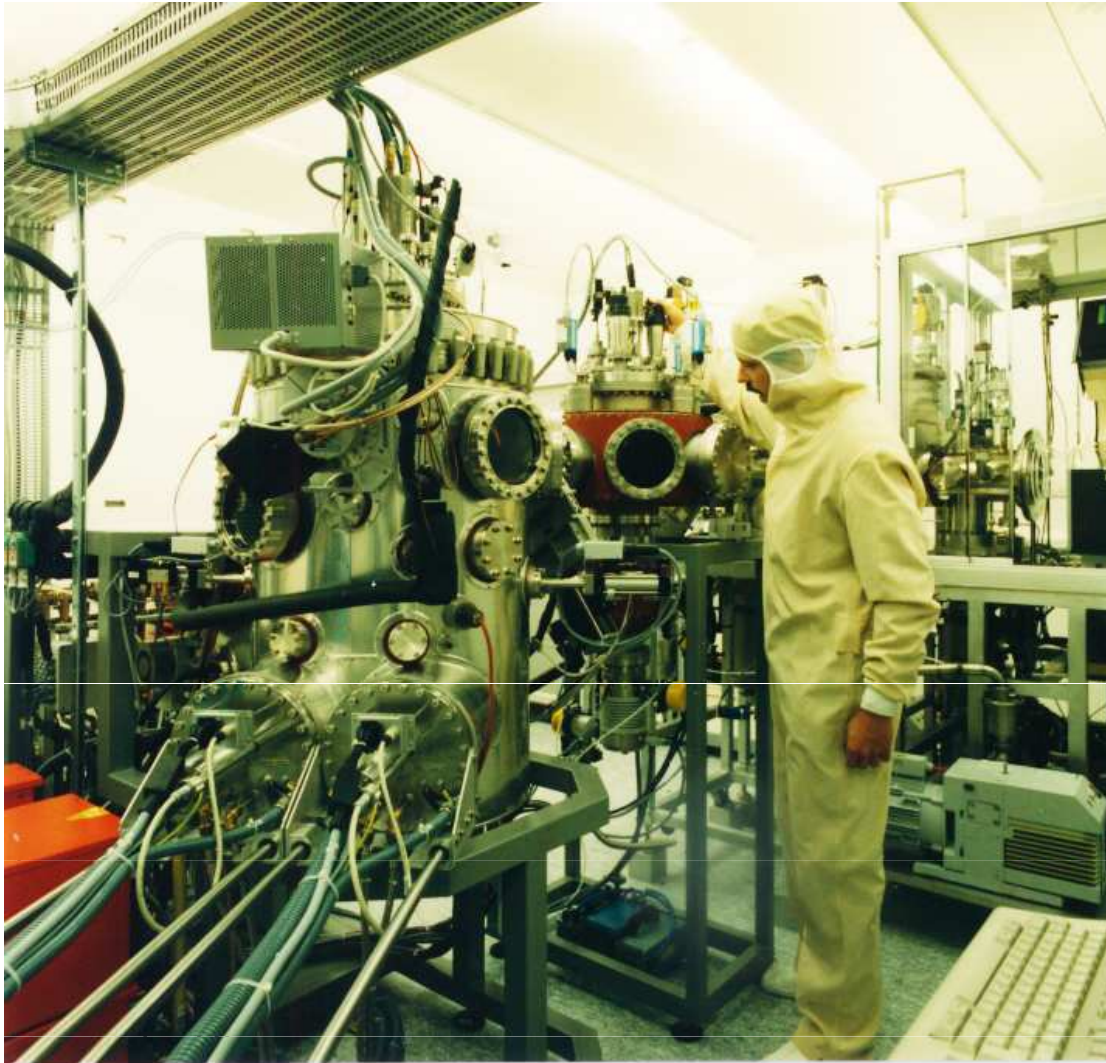
↔ with Si ↔

Possible
(nature of the bandgap irrelevant)

Monolithic Integration (Hetero-Epitaxy)



Molecular Beam Epitaxy (MBE)



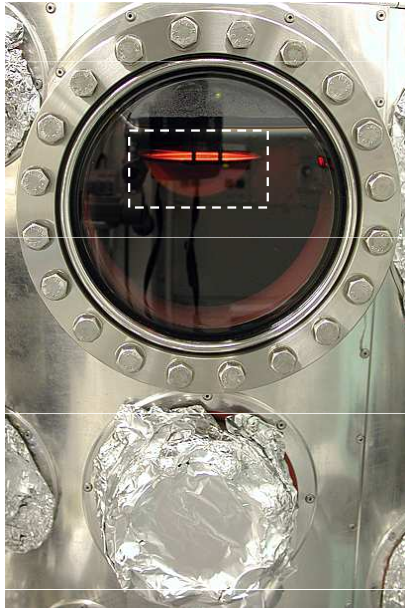
Requirements:

- Many (> 1000) few-atoms thick layers of alloy materials
- Atomic control of layer thickness
- Atomically flat layer interfaces

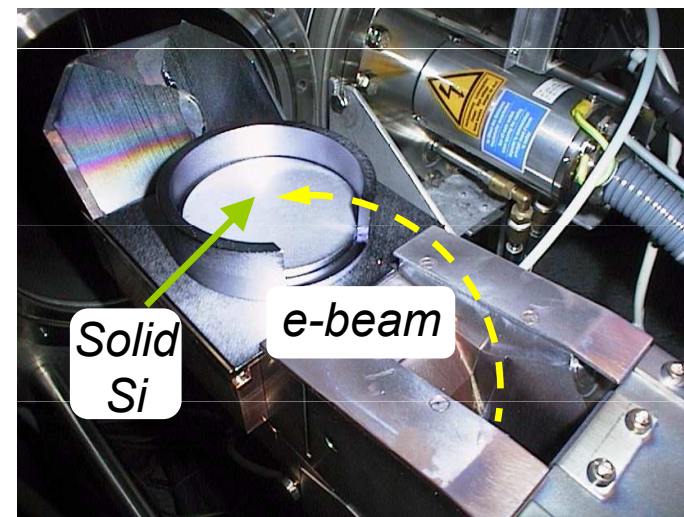
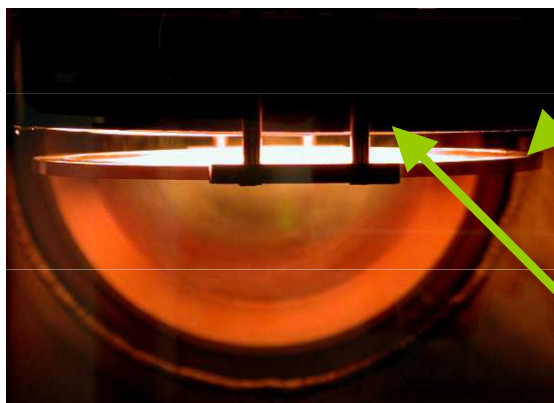
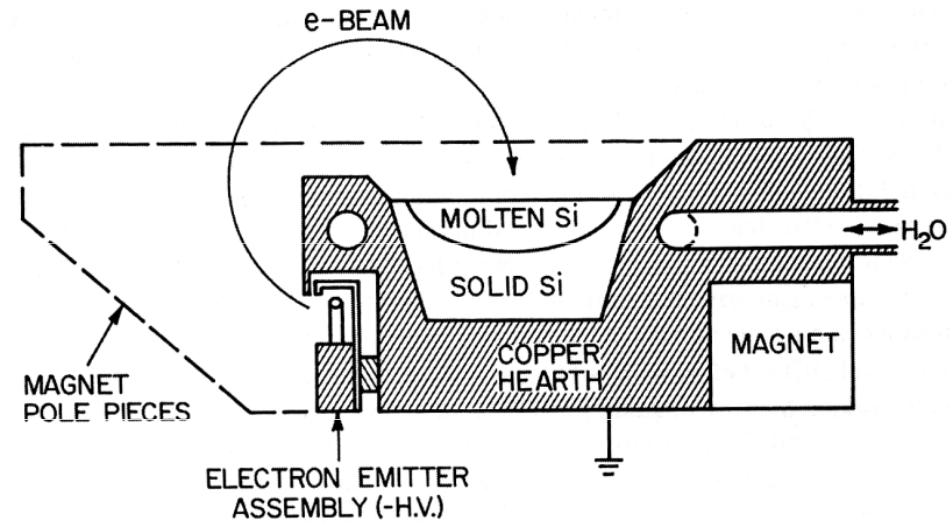
➤ Typical growth rates ($\sim \text{\AA}/\text{s}$)

Molecular Beam Epitaxy (MBE)

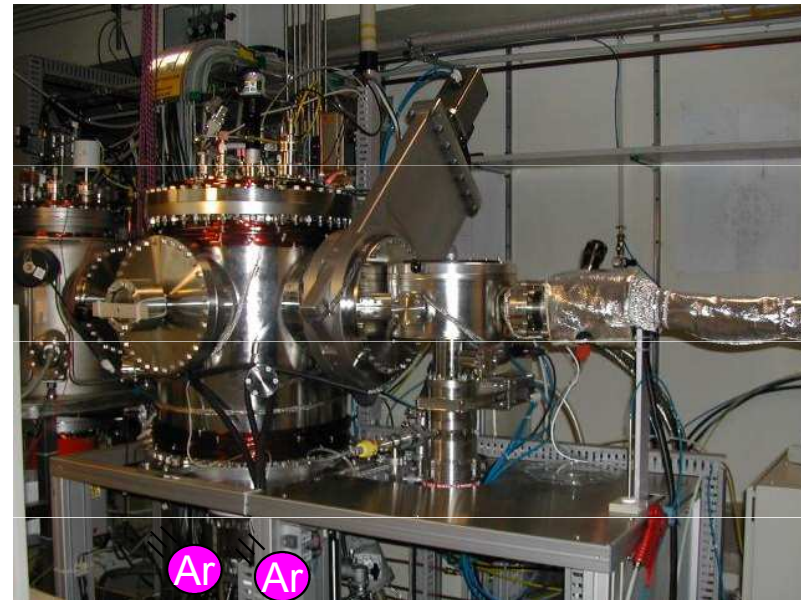
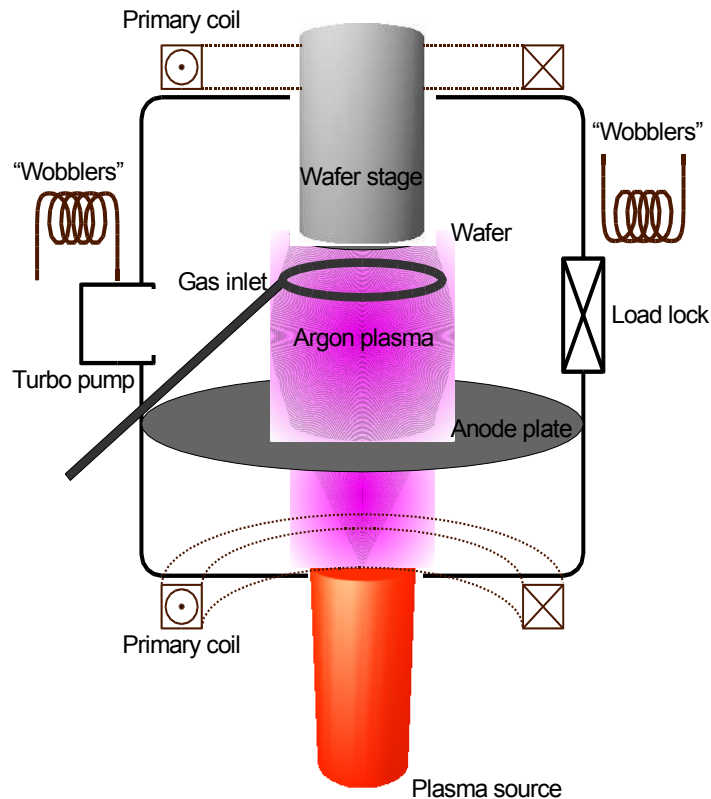
Growth chamber



Electron beam evaporation Si and Ge sources



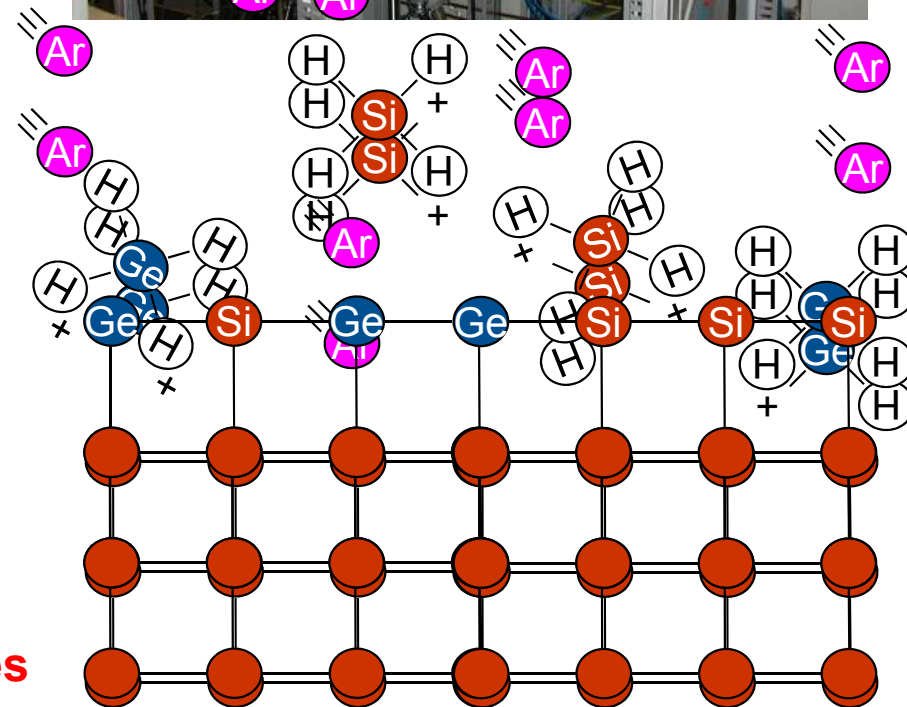
Low-Energy Plasma Enhanced Chemical Vapor Deposition



Principle of low-energy plasma-enhanced CVD:
High-current low-voltage arc discharge

SiH_4 and GeH_4 are transformed into highly reactive radicals

Very high growth rates ($0.5 \mu\text{m}/\text{min}$) possible at low substrate temperatures



Characterization of Epitaxial Structures

■ **Structural:**

- Reflection high energy electron diffraction (RHEED)
- Optical reflection spectroscopy
- X-ray diffraction
- Transmission electron microscopy
- Secondary ion mass spectrometry (SIMS)
- Rutherford backscattering spectrometry (RBS)
- Scanning Tunneling Microscopy
- Atomic Force Microscopy

■ **Optical:**

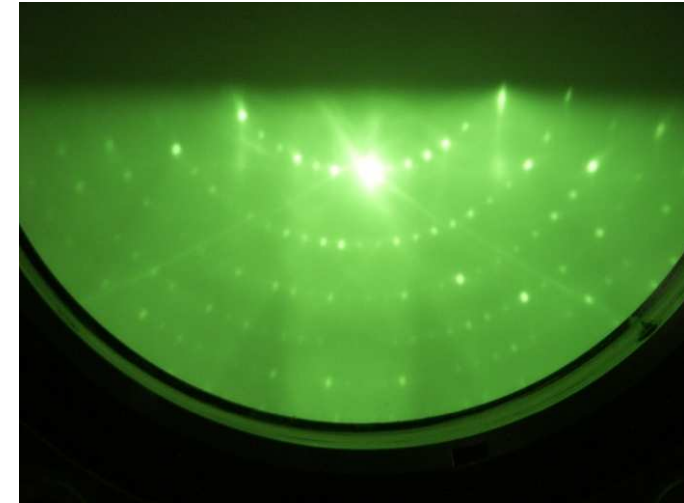
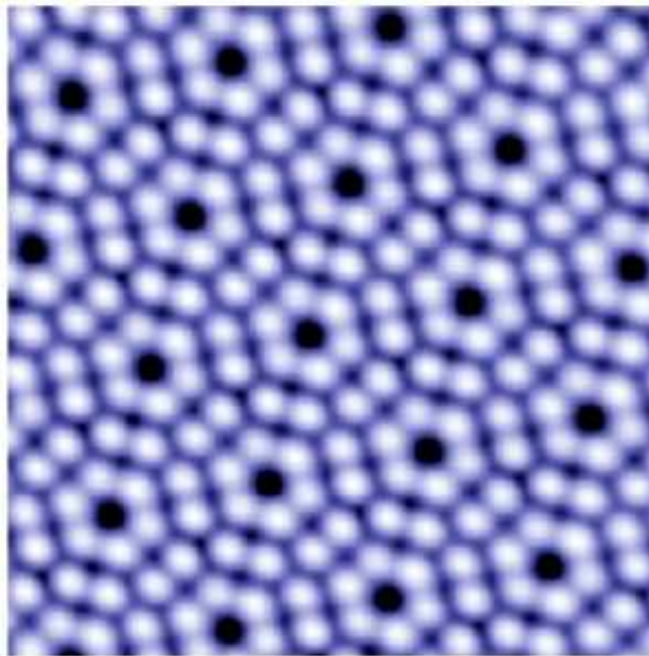
- Reflection & transmission
- Photoluminescence
- Raman scattering

■ **Electrical:**

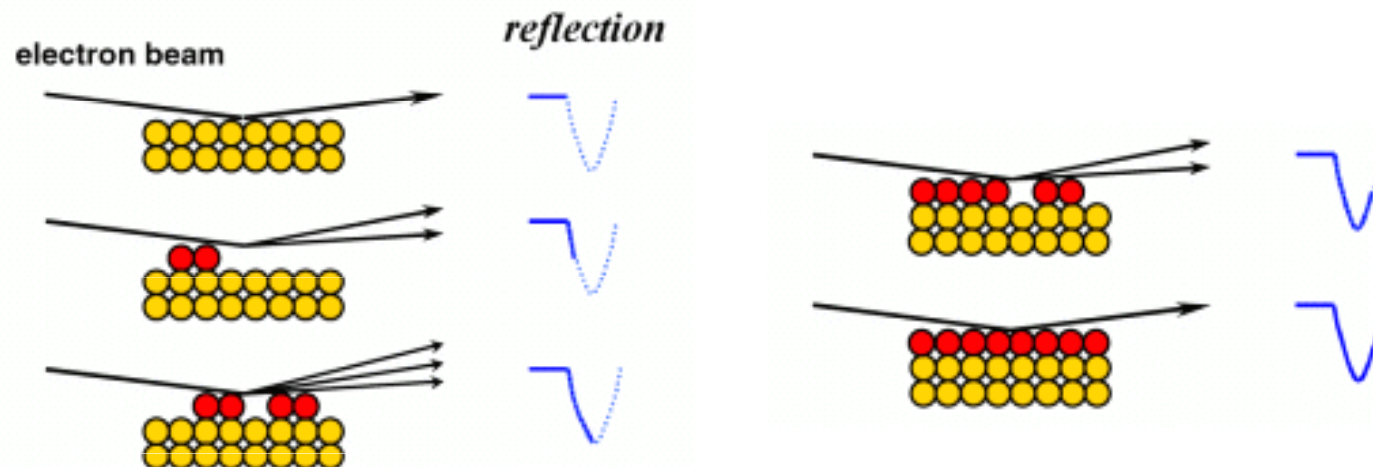
- Conductivity & Hall effect

Reflective High Energy Electron Diffraction (RHEED)

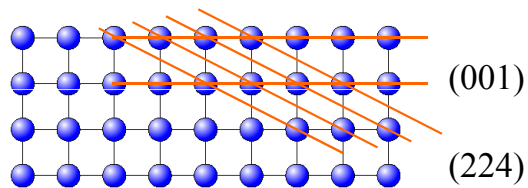
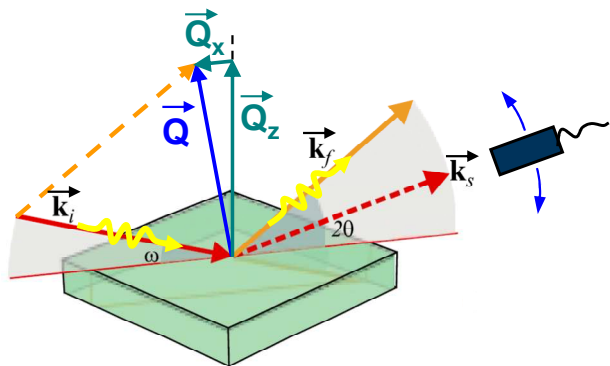
RHEED Pattern of Si(111)-7x7



Incident electron beam
along $\langle 11-2 \rangle$ azimuth

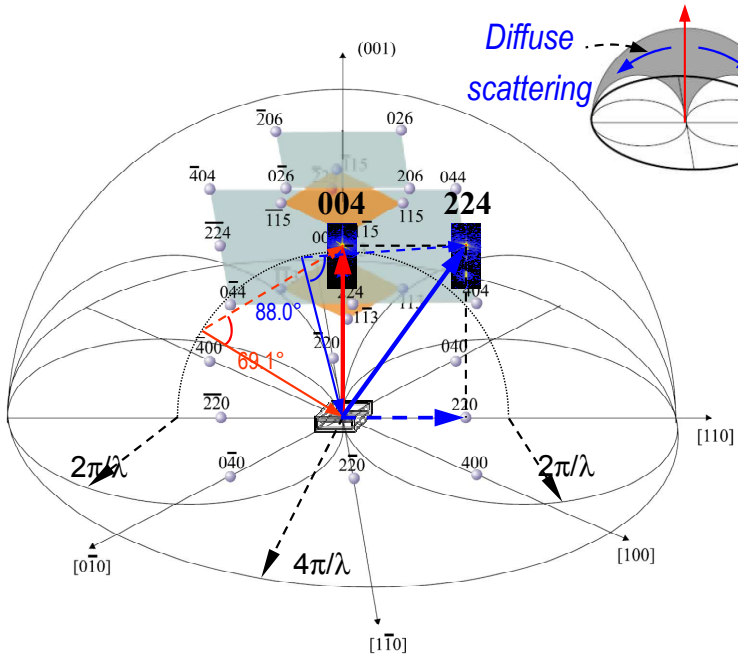


High-Resolution X-Ray Diffraction (HRXRD)

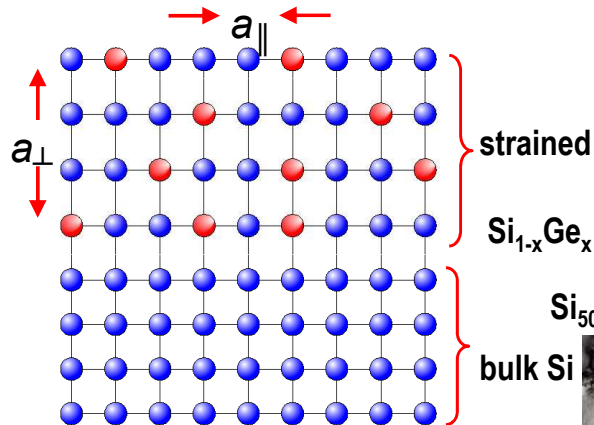


Truncation rod

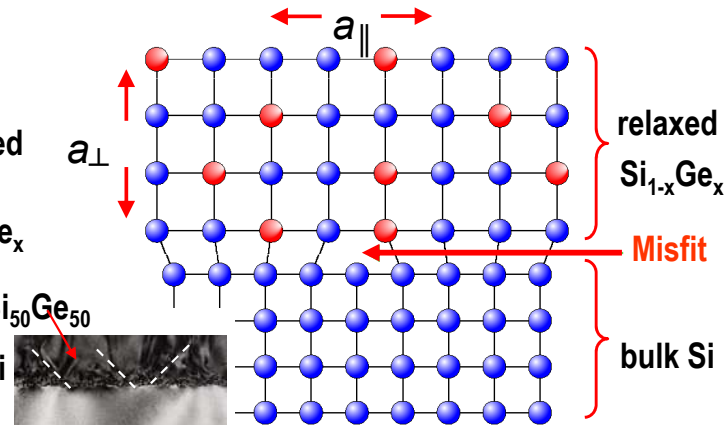
Diffuse scattering



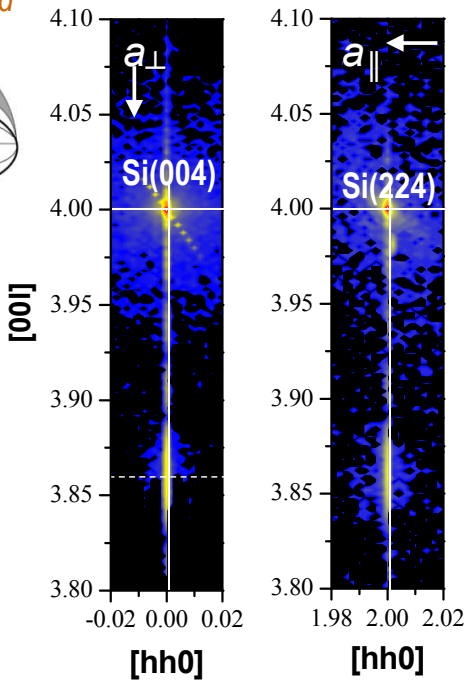
Strained SiGe on Si substrate



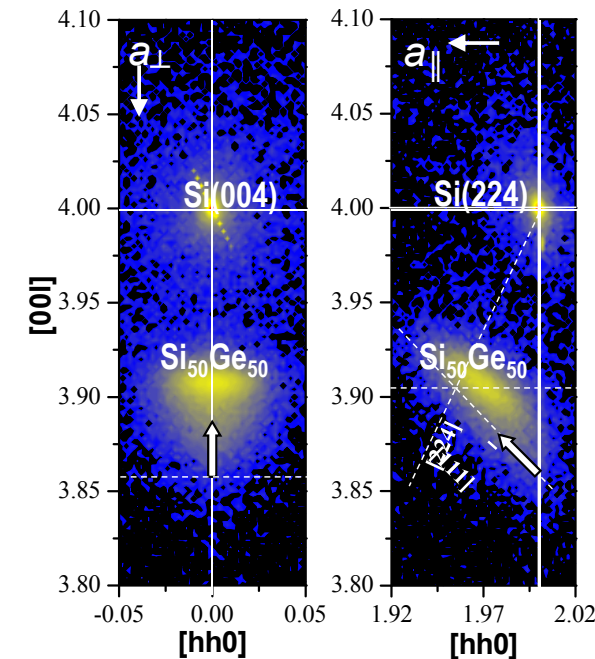
Relaxed SiGe on Si substrate



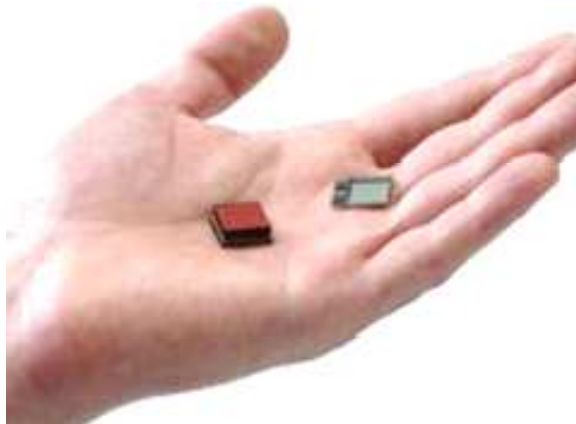
20 nm Si₅₀Ge₅₀



200 nm Si₅₀Ge₅₀



Motivation: Integrated Miniaturized X-ray Systems



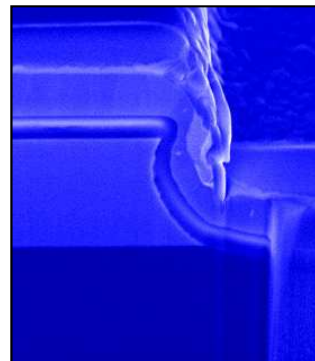
“NEXRAY”

- **Next Generation X-Ray Systems**
- High resolution/sensitivity
- Ge as conversion layer
- No bump-bonding (**monolithic integration**)

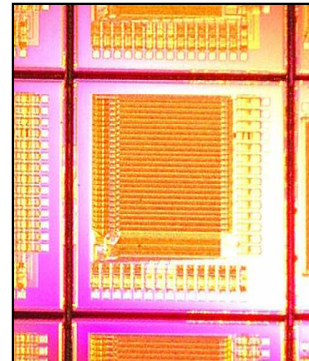
Fast, programmable
X-ray sources



Ge layers for high-
energy X-ray detection



Single-photon solid-
state X-ray detection

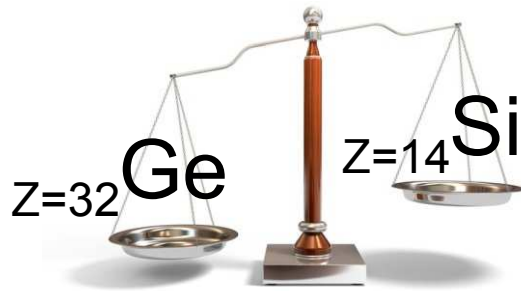


Phase contrast
X-ray imaging

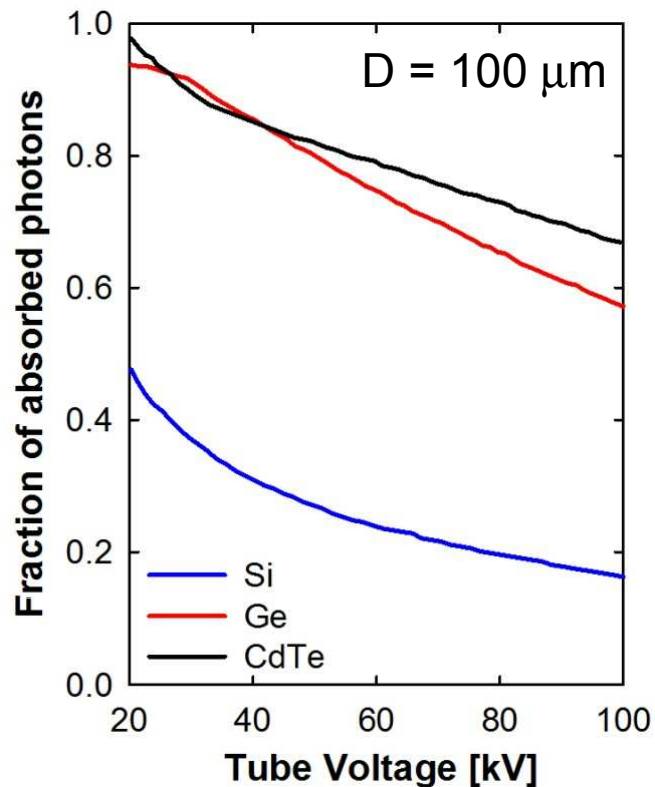
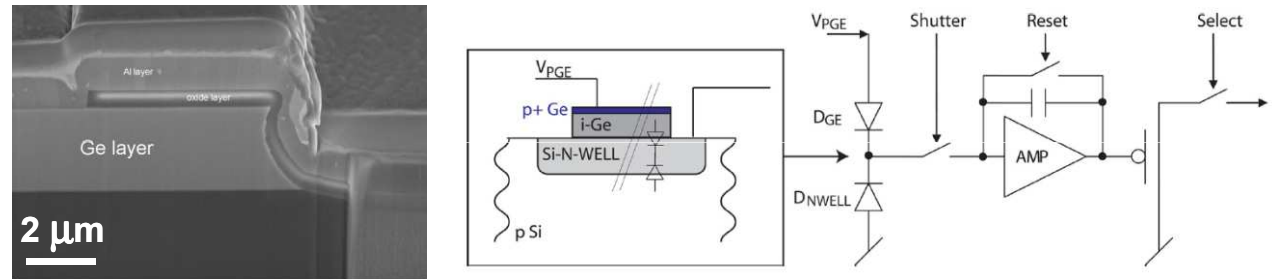


Motivation: Next Generation X-Ray Detectors

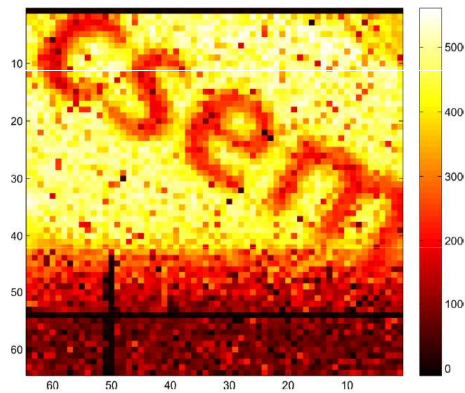
- Why Germanium?



- Monolithic integration of a 3 μm Ge film with CMOS for IR radiation was demonstrated at ETHZ/CSEM



64x64 pixel IR sensor with integrated Ge photodiodes

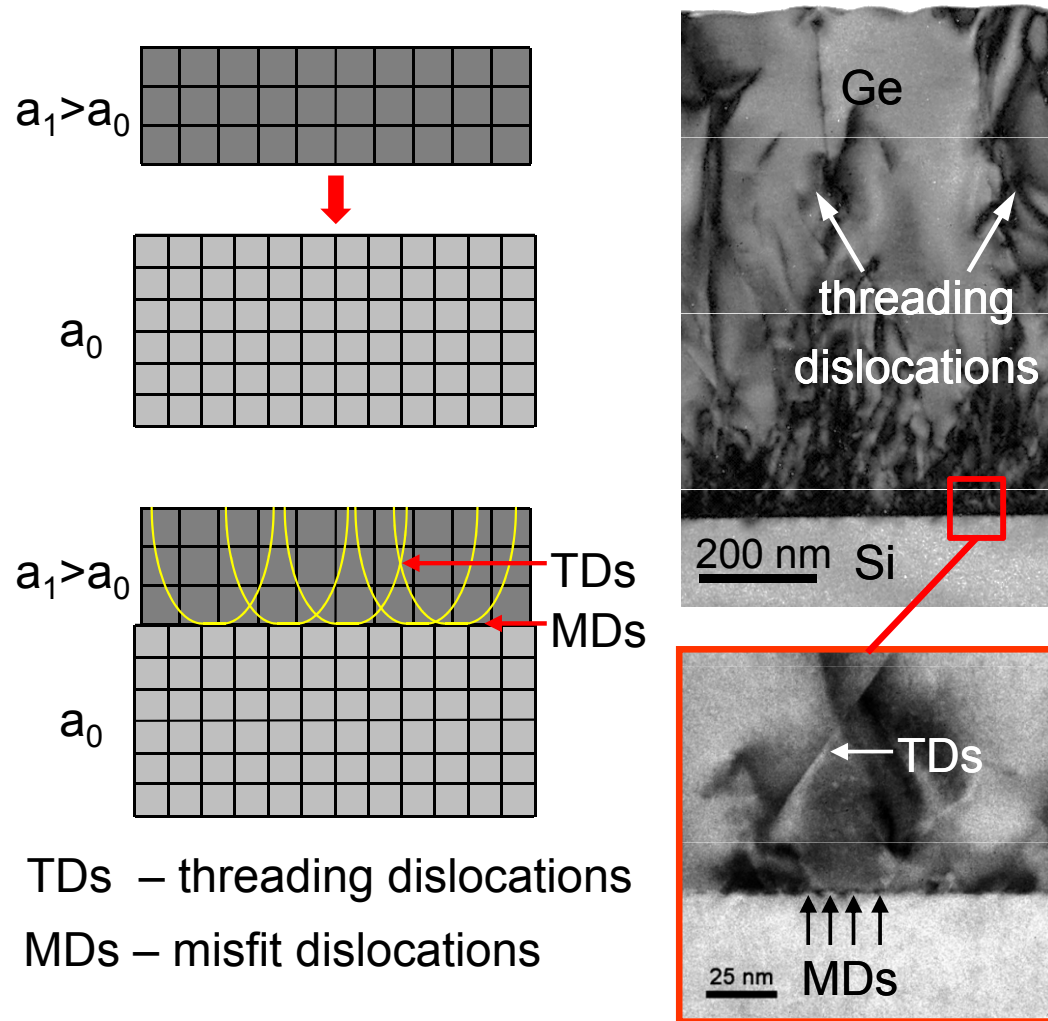


R. Kaufmann *et al.*, J. Appl. Phys. **110**, 023107 (2011)

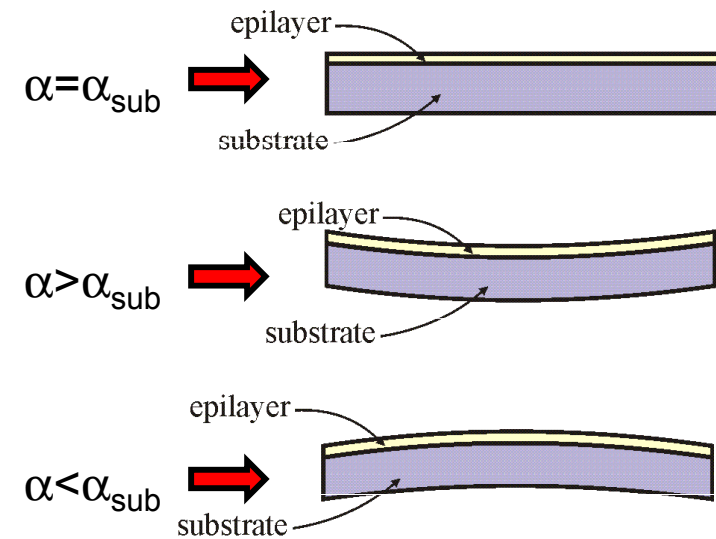
For X-rays \rightarrow **SUPER THICK (> 50 μm !!!)** high quality (i.e. dislocations, uniformity) Ge epilayers

Key Problems of Hetero-Epitaxy

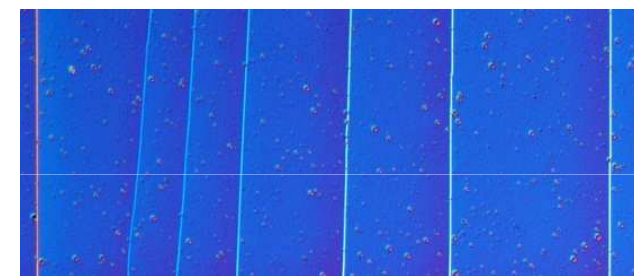
1. Dislocations (lattice mismatch)



2. Wafer Bowing & Cracks (thermal mismatch)



Nomarski top view micrograph



30 μm Ge/Si(001)

Scaling Hetero-Epitaxy from Layers to Three-Dimensional Crystals

Claudiu V. Falub *et al.*

Science **335**, 1330 (2012);

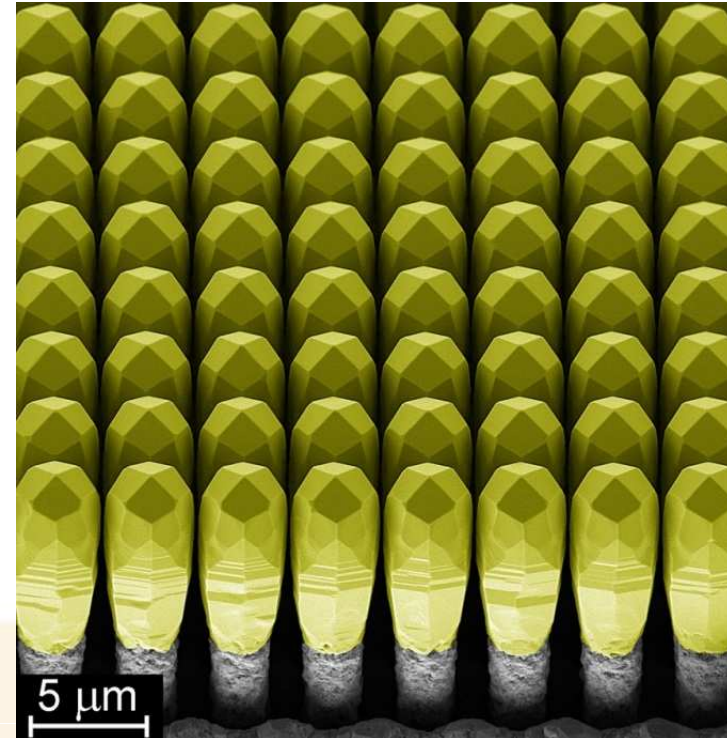
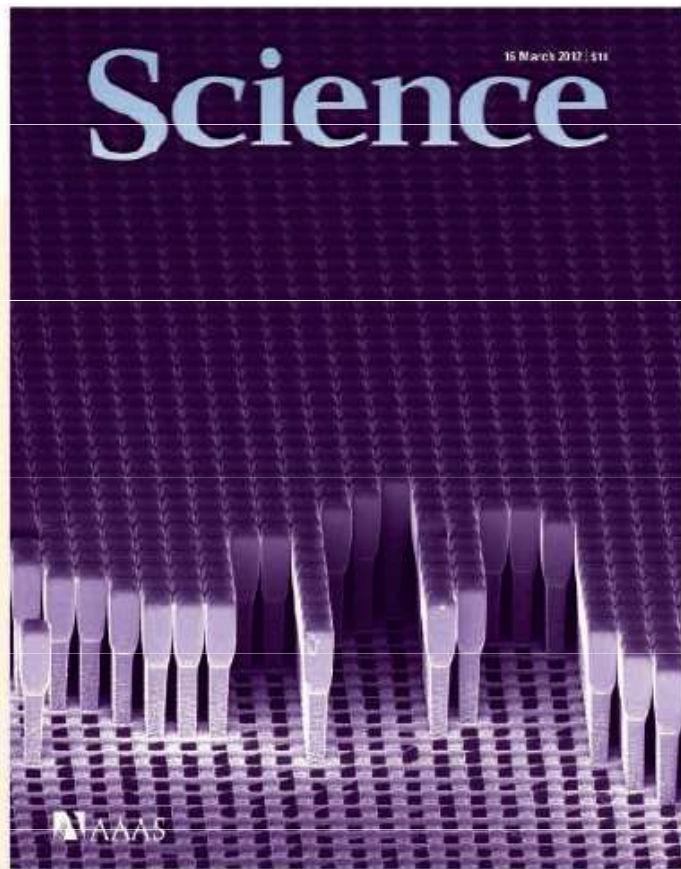
DOI: 10.1126/science.1217666

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COVER

False-colored scanning electron micrograph of ~8-micrometer-tall germanium crystals, separated by finite gaps, grown onto silicon pillars. In structures like this one, wafer bowing and layer cracking are absent, allowing single-crystal integration of different materials onto a silicon substrate, which serves as a platform for many applications, such as multiple-junction solar cells, x-ray and particle detectors, or power electronic devices. See page 1330.

Image: Claudiu V. Falub, Laboratory for Solid State Physics, Swiss Federal Institute of Technology (ETH-Zürich)

An aerial, black and white photograph of a dense urban skyline, likely New York City. The image shows a vast array of skyscrapers and buildings of varying heights and architectural styles, packed closely together. The perspective is from a high angle, looking down on the city. The text "To Be Continued..." is overlaid in the center in a bright yellow, bold, sans-serif font.

To Be Continued...

Conclusions

- Silicon age has still got tremendous potential for further progress ⇒ **its end is not near, yet!**
- Moore's law may eventually no longer decide the pace of microelectronics progress.
- **“More than Moore”** will be the new driving force.

Thank you for your attention !

Khumjung, Himalaya, Nepal, November 2003